

**9-Mbit (256 K × 36/512 K × 18)  
Pipelined SRAM**

**Features**

- Supports bus operation up to 250 MHz
- Available speed grades: 250, 200, and 166 MHz
- Registered inputs and outputs for pipelined operation
- 3.3 V core power supply (V<sub>DD</sub>)
- 2.5 V/3.3 V I/O operation (V<sub>DDQ</sub>)
- Fast clock-to-output times
  - 2.8 ns (for 250 MHz device)
- Provide high performance 3-1-1-1 access rate
- User selectable burst counter supporting Intel® Pentium® interleaved or linear burst sequences
- Separate processor and controller address strobes
- Synchronous self-timed writes
- Asynchronous output enable
- Single cycle chip deselect
- Available in Pb-free 100-pin TQFP package, Pb-free and non Pb-free 119-ball BGA package, and 165-ball FBGA package
- TQFP available with 3-chip enable and 2-chip enable
- IEEE 1149.1 JTAG-compatible boundary scan

**Functional Description**

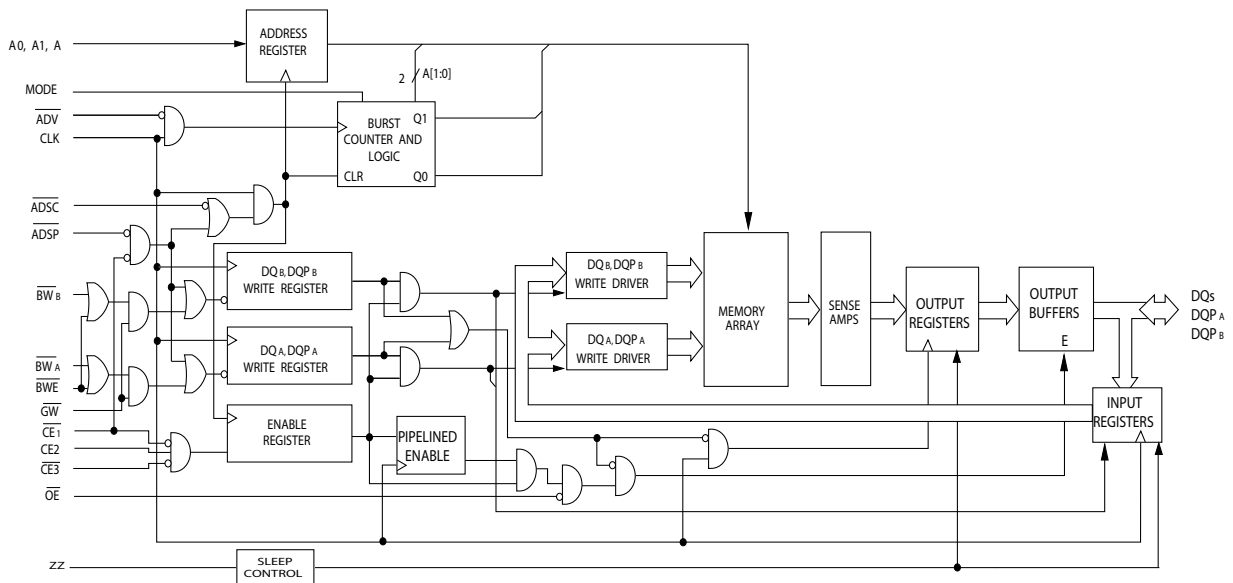
The CY7C1360C/CY7C1362C SRAM<sup>[1]</sup> integrates 256 K × 36 and 512 K × 18 SRAM cells with advanced synchronous peripheral circuitry and a two-bit counter for internal burst operation. All synchronous inputs are gated by registers controlled by a positive-edge-triggered clock input (CLK). The synchronous inputs include all addresses, all data inputs, address-pipelining chip enable (CE<sub>1</sub>), depth-expansion chip enables (CE<sub>2</sub> and CE<sub>3</sub><sup>[2]</sup>), burst control inputs (ADSC, ADSP, and ADV), write enables (BW<sub>X</sub>, and BWE), and global write (GW). Asynchronous inputs include the output enable (OE) and the ZZ pin.

Addresses and chip enables are registered at the rising edge of clock when either address strobe processor (ADSP) or address strobe controller (ADSC) are active. Subsequent burst addresses can be internally generated as controlled by the advance pin (ADV).

Address, data inputs, and write controls are registered on-chip to initiate a self-timed write cycle. This part supports byte write operations (see “Pin Definitions” on page 8 and “Truth Table” on page 11 for further details). Write cycles can be one to two or four bytes wide as controlled by the byte write control inputs. GW when active LOW causes all bytes to be written.

The CY7C1360C/CY7C1362C operate from a +3.3 V core power supply while all outputs may operate with either a +2.5 or +3.3 V supply. All inputs and outputs are JEDEC-standard JESD8-5-compatible.

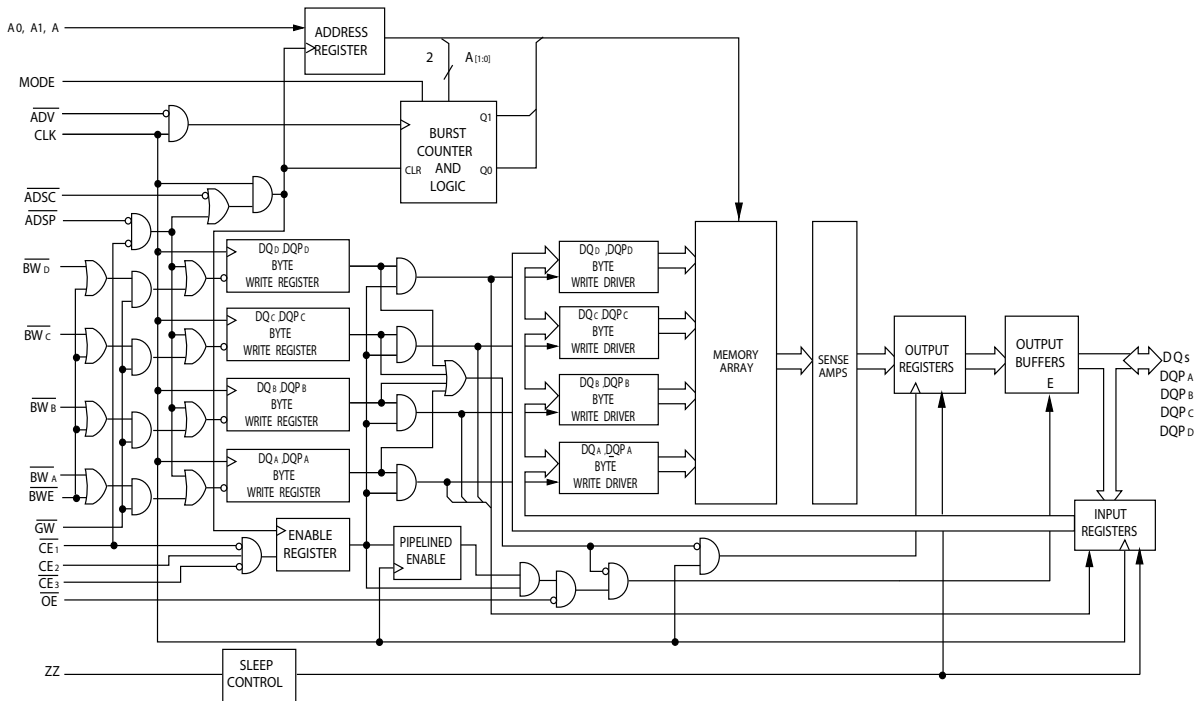
**Logic Block Diagram – CY7C1362C (512 K × 18)**



**Notes**

1. For best-practices recommendations, refer to the Cypress application note *System Design Guidelines* on [www.cypress.com](http://www.cypress.com).
2. CE<sub>3</sub> is for A version of TQFP (3 Chip Enable option) and 165-ball FBGA package only. 119-ball BGA is offered only in 2 Chip Enable.

Logic Block Diagram – CY7C1360C (256 K × 36)



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**Selection Guide**

Description	250 MHz	200 MHz	166 MHz	Unit
Maximum access time	2.8	3.0	3.5	ns
Maximum operating current	250	220	180	mA
Maximum CMOS standby current	40	40	40	mA

**Pin Configurations**

**Figure 1. 100-pin TQFP (3 Chip Enables - A Version)**

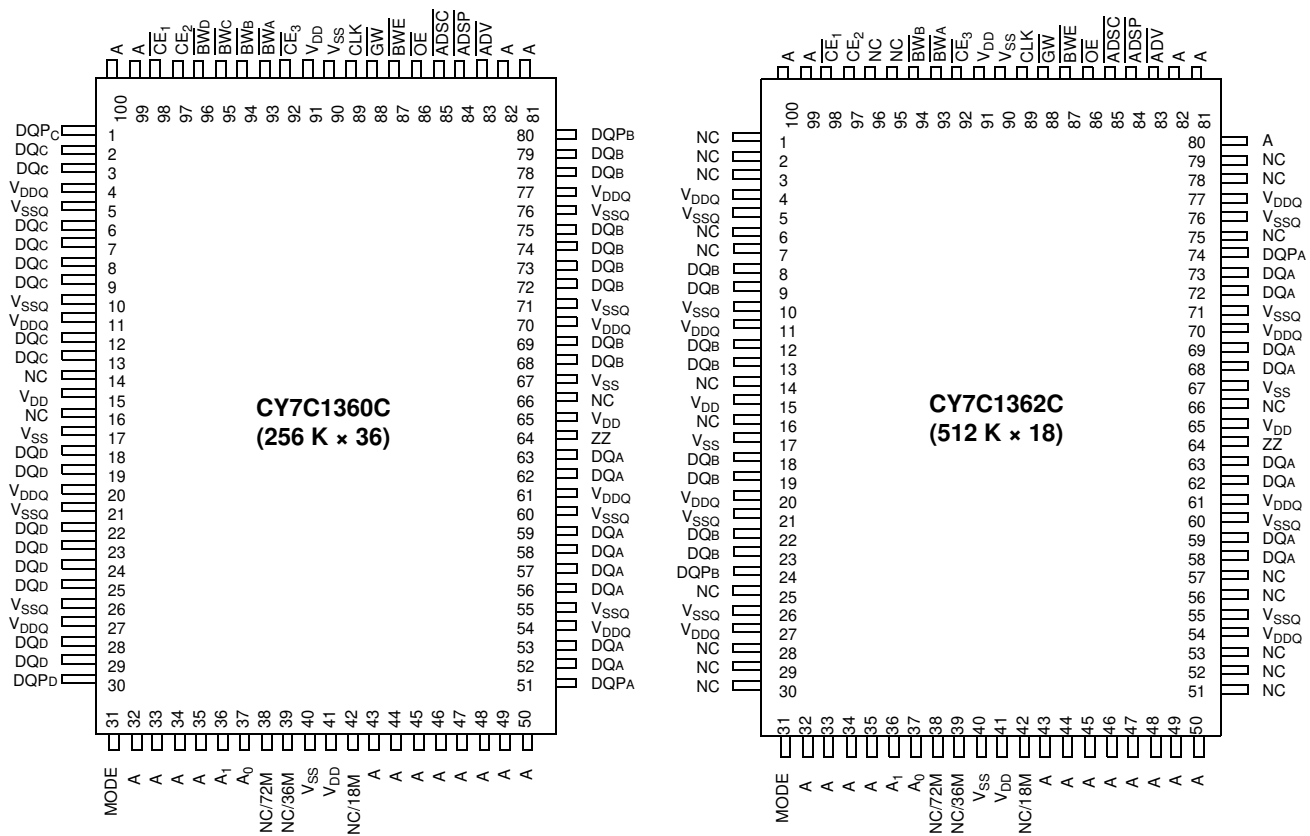
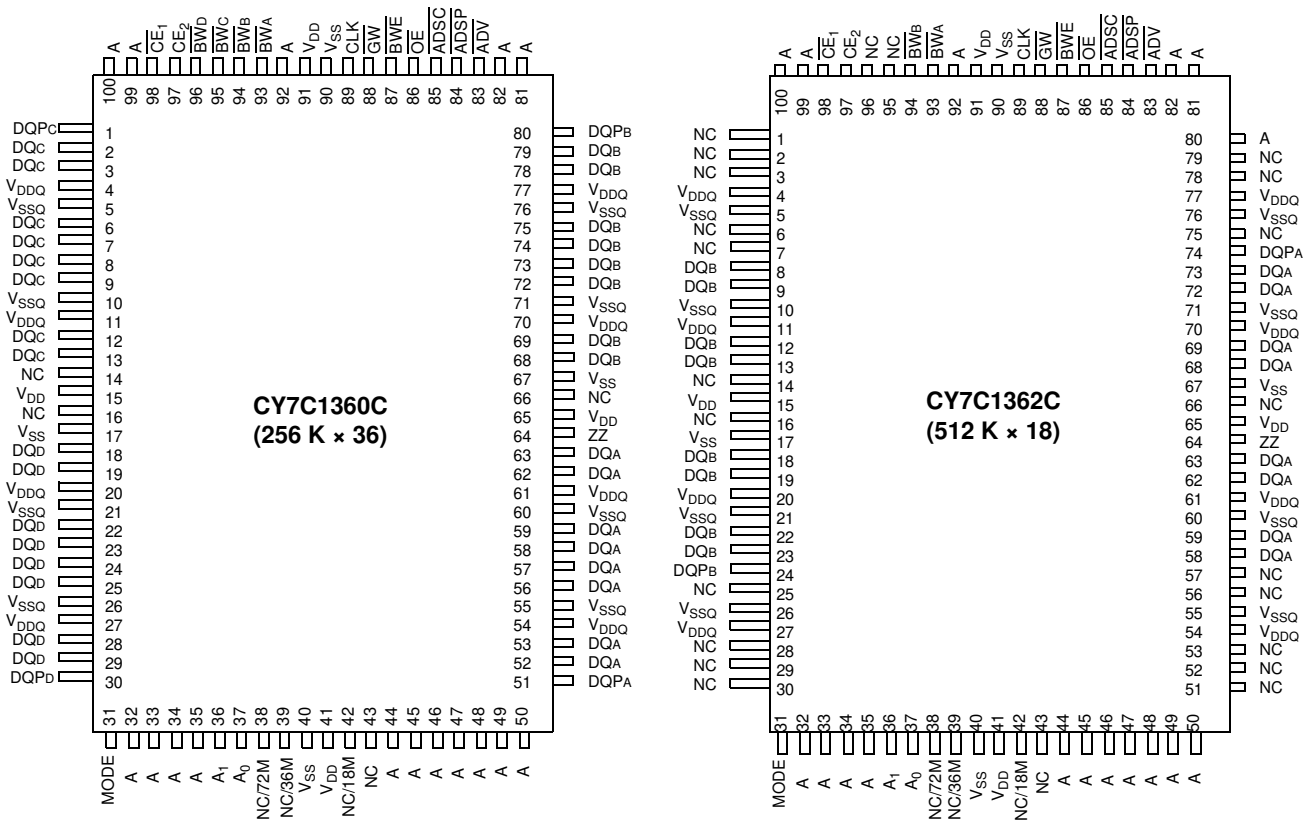


Figure 2. 100-pin TQFP (2 Chip Enables - AJ Version)



**Figure 3. 119-ball BGA (2 Chip Enables with JTAG)**
**CY7C1360C (256 K × 36)**

	1	2	3	4	5	6	7
<b>A</b>	V <sub>DDQ</sub>	A	A	$\overline{\text{ADSP}}$	A	A	V <sub>DDQ</sub>
<b>B</b>	NC/288M	CE <sub>2</sub>	A	$\overline{\text{ADSC}}$	A	A	NC/576M
<b>C</b>	NC/144M	A	A	V <sub>DD</sub>	A	A	NC/1G
<b>D</b>	DQ <sub>C</sub>	DQP <sub>C</sub>	V <sub>SS</sub>	NC	V <sub>SS</sub>	DQP <sub>B</sub>	DQ <sub>B</sub>
<b>E</b>	DQ <sub>C</sub>	DQ <sub>C</sub>	V <sub>SS</sub>	$\overline{\text{CE}}_1$	V <sub>SS</sub>	DQ <sub>B</sub>	DQ <sub>B</sub>
<b>F</b>	V <sub>DDQ</sub>	DQ <sub>C</sub>	V <sub>SS</sub>	$\overline{\text{OE}}$	V <sub>SS</sub>	DQ <sub>B</sub>	V <sub>DDQ</sub>
<b>G</b>	DQ <sub>C</sub>	DQ <sub>C</sub>	$\overline{\text{BW}}_C$	$\overline{\text{ADV}}$	$\overline{\text{BW}}_B$	DQ <sub>B</sub>	DQ <sub>B</sub>
<b>H</b>	DQ <sub>C</sub>	DQ <sub>C</sub>	V <sub>SS</sub>	$\overline{\text{GW}}$	V <sub>SS</sub>	DQ <sub>B</sub>	DQ <sub>B</sub>
<b>J</b>	V <sub>DDQ</sub>	V <sub>DD</sub>	NC	V <sub>DD</sub>	NC	V <sub>DD</sub>	V <sub>DDQ</sub>
<b>K</b>	DQ <sub>D</sub>	DQ <sub>D</sub>	V <sub>SS</sub>	CLK	V <sub>SS</sub>	DQ <sub>A</sub>	DQ <sub>A</sub>
<b>L</b>	DQ <sub>D</sub>	DQ <sub>D</sub>	$\overline{\text{BW}}_D$	NC	$\overline{\text{BW}}_A$	DQ <sub>A</sub>	DQ <sub>A</sub>
<b>M</b>	V <sub>DDQ</sub>	DQ <sub>D</sub>	V <sub>SS</sub>	$\overline{\text{BWE}}$	V <sub>SS</sub>	DQ <sub>A</sub>	V <sub>DDQ</sub>
<b>N</b>	DQ <sub>D</sub>	DQ <sub>D</sub>	V <sub>SS</sub>	A1	V <sub>SS</sub>	DQ <sub>A</sub>	DQ <sub>A</sub>
<b>P</b>	DQ <sub>D</sub>	DQP <sub>D</sub>	V <sub>SS</sub>	A0	V <sub>SS</sub>	DQP <sub>A</sub>	DQ <sub>A</sub>
<b>R</b>	NC	A	MODE	V <sub>DD</sub>	NC	A	NC
<b>T</b>	NC	NC/72M	A	A	A	NC/36M	ZZ
<b>U</b>	V <sub>DDQ</sub>	TMS	TDI	TCK	TDO	NC	V <sub>DDQ</sub>

**CY7C1362C (512 K × 18)**

	1	2	3	4	5	6	7
<b>A</b>	V <sub>DDQ</sub>	A	A	$\overline{\text{ADSP}}$	A	A	V <sub>DDQ</sub>
<b>B</b>	NC/288M	CE <sub>2</sub>	A	$\overline{\text{ADSC}}$	A	A	NC/576M
<b>C</b>	NC/144M	A	A	V <sub>DD</sub>	A	A	NC/1G
<b>D</b>	DQ <sub>B</sub>	NC	V <sub>SS</sub>	NC	V <sub>SS</sub>	DQP <sub>A</sub>	NC
<b>E</b>	NC	DQ <sub>B</sub>	V <sub>SS</sub>	$\overline{\text{CE}}_1$	V <sub>SS</sub>	NC	DQ <sub>A</sub>
<b>F</b>	V <sub>DDQ</sub>	NC	V <sub>SS</sub>	$\overline{\text{OE}}$	V <sub>SS</sub>	DQ <sub>A</sub>	V <sub>DDQ</sub>
<b>G</b>	NC	DQ <sub>B</sub>	$\overline{\text{BW}}_B$	$\overline{\text{ADV}}$	V <sub>SS</sub>	NC	DQ <sub>A</sub>
<b>H</b>	DQ <sub>B</sub>	NC	V <sub>SS</sub>	$\overline{\text{GW}}$	V <sub>SS</sub>	DQ <sub>A</sub>	NC
<b>J</b>	V <sub>DDQ</sub>	V <sub>DD</sub>	NC	V <sub>DD</sub>	NC	V <sub>DD</sub>	V <sub>DDQ</sub>
<b>K</b>	NC	DQ <sub>B</sub>	V <sub>SS</sub>	CLK	V <sub>SS</sub>	NC	DQ <sub>A</sub>
<b>L</b>	DQ <sub>B</sub>	NC	V <sub>SS</sub>	NC	$\overline{\text{BW}}_A$	DQ <sub>A</sub>	NC
<b>M</b>	V <sub>DDQ</sub>	DQ <sub>B</sub>	V <sub>SS</sub>	$\overline{\text{BWE}}$	V <sub>SS</sub>	NC	V <sub>DDQ</sub>
<b>N</b>	DQ <sub>B</sub>	NC	V <sub>SS</sub>	A1	V <sub>SS</sub>	DQ <sub>A</sub>	NC
<b>P</b>	NC	DQP <sub>B</sub>	V <sub>SS</sub>	A0	V <sub>SS</sub>	NC	DQ <sub>A</sub>
<b>R</b>	NC	A	MODE	V <sub>DD</sub>	NC	A	NC
<b>T</b>	NC/72M	A	A	NC/36M	A	A	ZZ
<b>U</b>	V <sub>DDQ</sub>	TMS	TDI	TCK	TDO	NC	V <sub>DDQ</sub>

**Figure 4. 165-ball FBGA (3 Chip Enables with JTAG)**
**CY7C1360C (256 K × 36)**

	1	2	3	4	5	6	7	8	9	10	11
<b>A</b>	NC/288M	A	$\overline{CE}_1$	$\overline{BW}_C$	$\overline{BW}_B$	$\overline{CE}_3$	$\overline{BWE}$	$\overline{ADSC}$	$\overline{ADV}$	A	NC
<b>B</b>	NC/144M	A	CE2	$\overline{BW}_D$	$\overline{BW}_A$	CLK	$\overline{GW}$	$\overline{OE}$	$\overline{ADSP}$	A	NC/576M
<b>C</b>	DQP <sub>C</sub>	NC	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC/1G	DQP <sub>B</sub>
<b>D</b>	DQ <sub>C</sub>	DQ <sub>C</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>B</sub>	DQ <sub>B</sub>
<b>E</b>	DQ <sub>C</sub>	DQ <sub>C</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>B</sub>	DQ <sub>B</sub>
<b>F</b>	DQ <sub>C</sub>	DQ <sub>C</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>B</sub>	DQ <sub>B</sub>
<b>G</b>	DQ <sub>C</sub>	DQ <sub>C</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>B</sub>	DQ <sub>B</sub>
<b>H</b>	NC	V <sub>SS</sub>	NC	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	NC	NC	ZZ
<b>J</b>	DQ <sub>D</sub>	DQ <sub>D</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>A</sub>	DQ <sub>A</sub>
<b>K</b>	DQ <sub>D</sub>	DQ <sub>D</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>A</sub>	DQ <sub>A</sub>
<b>L</b>	DQ <sub>D</sub>	DQ <sub>D</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>A</sub>	DQ <sub>A</sub>
<b>M</b>	DQ <sub>D</sub>	DQ <sub>D</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>A</sub>	DQ <sub>A</sub>
<b>N</b>	DQP <sub>D</sub>	NC	V <sub>DDQ</sub>	V <sub>SS</sub>	NC	NC/18M	NC	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	DQP <sub>A</sub>
<b>P</b>	NC	NC/72M	A	A	TDI	A1	TDO	A	A	A	A
<b>R</b>	MODE	NC/36M	A	A	TMS	A0	TCK	A	A	A	A

**CY7C1362C (512 K × 18)**

	1	2	3	4	5	6	7	8	9	10	11
<b>A</b>	NC/288M	A	$\overline{CE}_1$	$\overline{BW}_B$	NC	$\overline{CE}_3$	$\overline{BWE}$	$\overline{ADSC}$	$\overline{ADV}$	A	A
<b>B</b>	NC/144M	A	CE2	NC	$\overline{BW}_A$	CLK	$\overline{GW}$	$\overline{OE}$	$\overline{ADSP}$	A	NC/576M
<b>C</b>	NC	NC	V <sub>DDQ</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DDQ</sub>	NC/1G	DQP <sub>A</sub>
<b>D</b>	NC	DQ <sub>B</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	DQ <sub>A</sub>
<b>E</b>	NC	DQ <sub>B</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	DQ <sub>A</sub>
<b>F</b>	NC	DQ <sub>B</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	DQ <sub>A</sub>
<b>G</b>	NC	DQ <sub>B</sub>	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	NC	DQ <sub>A</sub>
<b>H</b>	NC	V <sub>SS</sub>	NC	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	NC	NC	ZZ
<b>J</b>	DQ <sub>B</sub>	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>A</sub>	NC
<b>K</b>	DQ <sub>B</sub>	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>A</sub>	NC
<b>L</b>	DQ <sub>B</sub>	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>A</sub>	NC
<b>M</b>	DQ <sub>B</sub>	NC	V <sub>DDQ</sub>	V <sub>DD</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>SS</sub>	V <sub>DD</sub>	V <sub>DDQ</sub>	DQ <sub>A</sub>	NC
<b>N</b>	DQP <sub>B</sub>	NC	V <sub>DDQ</sub>	V <sub>SS</sub>	NC	NC/18M	NC	V <sub>SS</sub>	V <sub>DDQ</sub>	NC	NC
<b>P</b>	NC	NC/72M	A	A	TDI	A1	TDO	A	A	A	A
<b>R</b>	MODE	NC/36M	A	A	TMS	A0	TCK	A	A	A	A

**Pin Definitions**

Name	I/O	Description
A <sub>0</sub> , A <sub>1</sub> , A	Input-synchronous	<b>Address inputs used to select one of the address locations.</b> Sampled at the rising edge of the CLK if ADSP or ADSC is active LOW, and CE <sub>1</sub> , CE <sub>2</sub> , and CE <sub>3</sub> <sup>[3]</sup> are sampled active. A <sub>1</sub> , A <sub>0</sub> are fed to the two-bit counter.
$\overline{BW}_A$ , $\overline{BW}_B$ $\overline{BW}_C$ , $\overline{BW}_D$	Input-synchronous	<b>Byte write select inputs, active LOW.</b> Qualified with $\overline{BWE}$ to conduct byte writes to the SRAM. Sampled on the rising edge of CLK.
GW	Input-synchronous	<b>Global write enable input, active LOW.</b> When asserted LOW on the rising edge of CLK, a global write is conducted (all bytes are written, regardless of the values on BW <sub>x</sub> and BWE).
$\overline{BWE}$	Input-synchronous	<b>Byte write enable input, active LOW.</b> Sampled on the rising edge of CLK. This signal must be asserted LOW to conduct a byte write.
CLK	Input-clock	<b>Clock input.</b> Used to capture all synchronous inputs to the device. Also used to increment the burst counter when ADV is asserted LOW, during a burst operation.
CE <sub>1</sub>	Input-synchronous	<b>Chip enable 1 input, active LOW.</b> Sampled on the rising edge of CLK. Used in conjunction with CE <sub>2</sub> and CE <sub>3</sub> <sup>[3]</sup> to select/deselect the device. ADSP is ignored if CE <sub>1</sub> is HIGH. CE <sub>1</sub> is sampled only when a new external address is loaded.
CE <sub>2</sub>	Input-synchronous	<b>Chip enable 2 input, active HIGH.</b> Sampled on the rising edge of CLK. Used in conjunction with CE <sub>1</sub> and CE <sub>3</sub> <sup>[3]</sup> to select/deselect the device. CE <sub>2</sub> is sampled only when a new external address is loaded.
CE <sub>3</sub> <sup>[3]</sup>	Input-synchronous	<b>Chip enable 3 input, active LOW.</b> Sampled on the rising edge of CLK. Used in conjunction with CE <sub>1</sub> and CE <sub>2</sub> to select/deselect the device. Not available for AJ package version. Not connected for BGA. Where referenced, $\overline{CE}_3$ <sup>[3]</sup> is assumed active throughout this document for BGA. CE <sub>3</sub> is sampled only when a new external address is loaded.
OE	Input-asynchronous	<b>Output enable, asynchronous input, active LOW.</b> Controls the direction of the I/O pins. When LOW, the I/O pins behave as outputs. When deasserted HIGH, I/O pins are tristated, and act as input data pins. OE is masked during the first clock of a read cycle when emerging from a deselected state.
ADV	Input-synchronous	<b>Advance input signal, sampled on the rising edge of CLK, active LOW.</b> When asserted, it automatically increments the address in a burst cycle.
ADSP	Input-synchronous	<b>Address strobe from processor, sampled on the rising edge of CLK, active LOW.</b> When asserted LOW, addresses presented to the device are captured in the address registers. A <sub>1</sub> , A <sub>0</sub> are also loaded into the burst counter. When ADSP and ADSC are both asserted, only ADSP is recognized. ADSP is ignored when CE <sub>1</sub> is deasserted HIGH.
ADSC	Input-synchronous	<b>Address strobe from controller, sampled on the rising edge of CLK, active LOW.</b> When asserted LOW, addresses presented to the device are captured in the address registers. A <sub>1</sub> , A <sub>0</sub> are also loaded into the burst counter. When ADSP and ADSC are both asserted, only ADSP is recognized.
ZZ	Input-asynchronous	<b>ZZ “sleep” input, active HIGH.</b> When asserted HIGH places the device in a non-time-critical “sleep” condition with data integrity preserved. For normal operation, this pin has to be LOW or left floating. ZZ pin has an internal pull-down.
DQs, DQP <sub>x</sub>	I/O-synchronous	<b>Bidirectional data I/O lines.</b> As inputs, they feed into an on-chip data register that is triggered by the rising edge of CLK. As outputs, they deliver the data contained in the memory location specified by the addresses presented during the previous clock rise of the read cycle. The direction of the pins is controlled by OE. When OE is asserted LOW, the pins behave as outputs. When HIGH, DQs and DQP <sub>x</sub> are placed in a tristate condition.
V <sub>DD</sub>	Power supply	<b>Power supply inputs to the core of the device.</b>
V <sub>SS</sub>	Ground	<b>Ground for the core of the device.</b>
V <sub>SSQ</sub>	I/O ground	<b>Ground for the I/O circuitry.</b>
V <sub>DDQ</sub>	I/O power supply	<b>Power supply for the I/O circuitry.</b>
MODE	Input-static	<b>Selects burst order.</b> When tied to GND selects linear burst sequence. When tied to V <sub>DD</sub> or left floating selects interleaved burst sequence. This is a strap pin and should remain static during device operation. Mode pin has an internal pull-up.

**Note**

3. CE<sub>3</sub> is for A version of TQFP (3 Chip Enable option) and 165-ball FBGA package only. 119-ball BGA is offered only in 2 Chip Enable.



**Pin Definitions** (continued)

Name	I/O	Description
TDO	JTAG serial output synchronous	<b>Serial data-out to the JTAG circuit.</b> Delivers data on the negative edge of TCK. If the JTAG feature is not being used, this pin should be disconnected. This pin is not available on TQFP packages.
TDI	JTAG serial input synchronous	<b>Serial data-in to the JTAG circuit.</b> Sampled on the rising edge of TCK. If the JTAG feature is not being used, this pin can be disconnected or connected to $V_{DD}$ . This pin is not available on TQFP packages.
TMS	JTAG serial input synchronous	<b>Serial data-in to the JTAG circuit.</b> Sampled on the rising edge of TCK. If the JTAG feature is not being used, this pin can be disconnected or connected to $V_{DD}$ . This pin is not available on TQFP packages.
TCK	JTAG-clock	<b>Clock input to the JTAG circuitry.</b> If the JTAG feature is not being used, this pin must be connected to $V_{SS}$ . This pin is not available on TQFP packages.
NC	–	<b>No connects.</b> Not internally connected to the die
NC (18,36, 72, 144, 288, 576, 1G)	–	<b>These pins are not connected.</b> They will be used for expansion to the 18M, 36M, 72M, 144M, 288M, 576M, and 1G densities.

**Functional Overview**

All synchronous inputs pass through input registers controlled by the rising edge of the clock. All data outputs pass through output registers controlled by the rising edge of the clock. Maximum access delay from the clock rise ( $t_{CO}$ ) is 2.8 ns (250 MHz device).

The CY7C1360C/CY7C1362C supports secondary cache in systems using either a linear or interleaved burst sequence. The interleaved burst order supports Pentium and i486™ processors. The linear burst sequence is suited for processors that use a linear burst sequence. The burst order is user selectable, and is determined by sampling the MODE input. Accesses can be initiated with either the processor address strobe (ADSP) or the controller address strobe (ADSC). Address advancement through the burst sequence is controlled by the ADV input. A two-bit on-chip wraparound burst counter captures the first address in a burst sequence and automatically increments the address for the rest of the burst access.

Byte write operations are qualified with the byte write enable (BWE) and byte write select ( $BW_X$ ) inputs. A global write enable (GW) overrides all byte write inputs and writes data to all four bytes. All writes are simplified with on-chip synchronous self-timed write circuitry.

Three synchronous chip selects ( $\overline{CE}_1$ ,  $CE_2$ ,  $\overline{CE}_3$ <sup>[4]</sup>) and an asynchronous output enable (OE) provide for easy bank selection and output tristate control. ADSP is ignored if  $\overline{CE}_1$  is HIGH.

**Single Read Accesses**

This access is initiated when the following conditions are satisfied at clock rise: (1) ADSP or ADSC is asserted LOW, (2)  $CE_1$ ,  $CE_2$ ,  $CE_3$ <sup>[4]</sup> are all asserted active, and (3) the write signals (GW, BWE) are all deasserted HIGH. ADSP is ignored if  $\overline{CE}_1$  is HIGH. The address presented to the address inputs (A) is stored into the address advancement logic and the address register while being presented to the memory array. The corresponding data is allowed to propagate to the input of

the output registers. At the rising edge of the next clock, the data is allowed to propagate through the output register and on the data bus within 2.8 ns (250 MHz device) if OE is active LOW. The only exception occurs when the SRAM is emerging from a deselected state to a selected state, its outputs are always tristated during the first cycle of the access. After the first cycle of the access, the outputs are controlled by the OE signal. Consecutive single read cycles are supported. After the SRAM is deselected at clock rise by the chip select and either ADSP or ADSC signals, its output tristates immediately.

**Single Write Accesses Initiated by ADSP**

This access is initiated when both of the following conditions are satisfied at clock rise: (1) ADSP is asserted LOW and (2)  $CE_1$ ,  $CE_2$ ,  $CE_3$ <sup>[4]</sup> are all asserted active. The address presented to A is loaded into the address register and the address advancement logic while being delivered to the memory array. The write signals (GW, BWE, and  $BW_X$ ) and ADV inputs are ignored during this first cycle.

ADSP-triggered write accesses require two clock cycles to complete. If GW is asserted LOW on the second clock rise, the data presented to the DQs inputs is written into the corresponding address location in the memory array. If GW is HIGH, then the write operation is controlled by BWE and  $BW_X$  signals. The CY7C1360C/CY7C1362C provides byte write capability that is described in the Write Cycle Descriptions table. Asserting the byte write enable input (BWE) with the selected byte write ( $BW_X$ ) input, will selectively write to only the desired bytes. Bytes not selected during a byte write operation remain unaltered. A synchronous self-timed write mechanism has been provided to simplify the write operations.

Because the CY7C1360C/CY7C1362C is a common I/O device, the output enable (OE) must be deasserted HIGH before presenting data to the DQs inputs. Doing so tristates the output drivers. As a safety precaution, DQs are automatically tristated whenever a Write cycle is detected, regardless of the state of OE.

**Note**

4.  $\overline{CE}_3$  is for A version of TQFP (3 Chip Enable option) and 165-ball FBGA package only. 119-ball BGA is offered only in 2 Chip Enable.

### Single Write Accesses Initiated by $\overline{\text{ADSC}}$

$\overline{\text{ADSC}}$  write accesses are initiated when the following conditions are satisfied: (1)  $\overline{\text{ADSC}}$  is asserted LOW, (2)  $\overline{\text{ADSP}}$  is deasserted HIGH, (3)  $\overline{\text{CE}}_1, \overline{\text{CE}}_2, \overline{\text{CE}}_3^{[5]}$  are all asserted active, and (4) the appropriate combination of the write inputs ( $\overline{\text{GW}}, \overline{\text{BWE}},$  and  $\overline{\text{BW}}_X$ ) are asserted active to conduct a write to the desired byte(s).  $\overline{\text{ADSC}}$ -triggered write accesses require a single clock cycle to complete. The address presented to A is loaded into the address register and the address advancement logic while being delivered to the memory array. The  $\overline{\text{ADV}}$  input is ignored during this cycle. If a global write is conducted, the data presented to the DQs is written into the corresponding address location in the memory core. If a byte write is conducted, only the selected bytes are written. Bytes not selected during a byte write operation remains unaltered. A synchronous self-timed write mechanism has been provided to simplify the write operations.

Because the CY7C1360C/CY7C1362C is a common I/O device, the output enable ( $\overline{\text{OE}}$ ) must be deasserted HIGH before presenting data to the DQs inputs. Doing so tristates the output drivers. As a safety precaution, DQs are automatically tristated whenever a write cycle is detected, regardless of the state of  $\overline{\text{OE}}$ .

### Burst Sequences

The CY7C1360C/CY7C1362C provides a two-bit wraparound counter, fed by  $A_1, A_0$ , that implements either an interleaved or linear burst sequence. The interleaved burst sequence is designed specifically to support Intel Pentium applications. The linear burst sequence is designed to support processors that follow a linear burst sequence. The burst sequence is user selectable through the MODE input.

**Table 3. ZZ Mode Electrical Characteristics**

Parameter	Description	Test Conditions	Min.	Max.	Unit
$I_{DDZZ}$	Sleep mode standby current	$ZZ \geq V_{DD} - 0.2 \text{ V}$	–	50	mA
$t_{ZZS}$	Device operation to ZZ	$ZZ \geq V_{DD} - 0.2 \text{ V}$	–	$2t_{CYC}$	ns
$t_{ZZREC}$	ZZ recovery time	$ZZ \leq 0.2 \text{ V}$	$2t_{CYC}$	–	ns
$t_{ZZI}$	ZZ active to sleep current	This parameter is sampled	–	$2t_{CYC}$	ns
$t_{RZZI}$	ZZ inactive to exit sleep current	This parameter is sampled	0	–	ns

Asserting  $\overline{\text{ADV}}$  LOW at clock rise automatically increments the burst counter to the next address in the burst sequence. Both read and write burst operations are supported.

### Sleep Mode

The ZZ input pin is an asynchronous input. Asserting ZZ places the SRAM in a power conservation 'sleep' mode. Two clock cycles are required to enter into or exit from this 'sleep' mode. While in this mode, data integrity is guaranteed. Accesses pending when entering the 'sleep' mode are not considered valid nor is the completion of the operation guaranteed. The device must be deselected prior to entering the 'sleep' mode.  $\overline{\text{CE}}_1, \overline{\text{CE}}_2, \overline{\text{CE}}_3^{[5]}, \overline{\text{ADSP}},$  and  $\overline{\text{ADSC}}$  must remain inactive for the duration of  $t_{ZZREC}$  after the ZZ input returns LOW.

**Table 1. Interleaved Burst Address Table (MODE = Floating or  $V_{DD}$ )**

First Address $A_1, A_0$	Second Address $A_1, A_0$	Third Address $A_1, A_0$	Fourth Address $A_1, A_0$
00	01	10	11
01	00	11	10
10	11	00	01
11	10	01	00

**Table 2. Linear Burst Address Table (MODE = GND)**

First Address $A_1, A_0$	Second Address $A_1, A_0$	Third Address $A_1, A_0$	Fourth Address $A_1, A_0$
00	01	10	11

**Note**

5.  $\overline{\text{CE}}_3$  is for A version of TQFP (3 Chip Enable option) and 165-ball FBGA package only. 119-ball BGA is offered only in 2 Chip Enable.

### Truth Table

The Truth Table for CY7C1360C and CY7C1362C follows.<sup>[6, 7, 8, 9, 10, 11]</sup>

Operation	Address Used	$\overline{CE}_1$	CE <sub>2</sub>	$\overline{CE}_3$	ZZ	$\overline{ADSP}$	$\overline{ADSC}$	$\overline{ADV}$	$\overline{WRITE}$	$\overline{OE}$	CLK	DQ
Deselect cycle, power-down	None	H	X	X	L	X	L	X	X	X	L-H	Tri-state
Deselect cycle, power-down	None	L	L	X	L	L	X	X	X	X	L-H	Tri-state
Deselect cycle, power-down	None	L	X	H	L	L	X	X	X	X	L-H	Tri-state
Deselect cycle, power-down	None	L	L	X	L	H	L	X	X	X	L-H	Tri-state
Deselect cycle, power-down	None	L	X	H	L	H	L	X	X	X	L-H	Tri-state
Sleep mode, power-down	None	X	X	X	H	X	X	X	X	X	X	Tri-state
READ cycle, begin burst	External	L	H	L	L	L	X	X	X	L	L-H	Q
READ cycle, begin burst	External	L	H	L	L	L	X	X	X	H	L-H	Tri-state
WRITE cycle, begin burst	External	L	H	L	L	H	L	X	L	X	L-H	D
READ cycle, begin burst	External	L	H	L	L	H	L	X	H	L	L-H	Q
READ cycle, begin burst	External	L	H	L	L	H	L	X	H	H	L-H	Tri-state
READ cycle, continue burst	Next	X	X	X	L	H	H	L	H	L	L-H	Q
READ cycle, continue burst	Next	X	X	X	L	H	H	L	H	H	L-H	Tri-state
READ cycle, continue burst	Next	H	X	X	L	X	H	L	H	L	L-H	Q
READ cycle, continue burst	Next	H	X	X	L	X	H	L	H	H	L-H	Tri-state
WRITE cycle, continue burst	Next	X	X	X	L	H	H	L	L	X	L-H	D
WRITE cycle, continue burst	Next	H	X	X	L	X	H	L	L	X	L-H	D
READ cycle, suspend burst	Current	X	X	X	L	H	H	H	H	L	L-H	Q
READ cycle, suspend burst	Current	X	X	X	L	H	H	H	H	H	L-H	Tri-state
READ cycle, suspend burst	Current	H	X	X	L	X	H	H	H	L	L-H	Q
READ cycle, suspend burst	Current	H	X	X	L	X	H	H	H	H	L-H	Tri-state
WRITE cycle, suspend burst	Current	X	X	X	L	H	H	H	L	X	L-H	D
WRITE cycle, suspend burst	Current	H	X	X	L	X	H	H	L	X	L-H	D

**Notes**

- 6. X = "Don't Care." H = Logic HIGH, L = Logic LOW.
- 7.  $\overline{WRITE}$  = L when any one or more byte write enable signals and  $\overline{BWE}$  = L or  $\overline{GW}$  = L.  $\overline{WRITE}$  = H when all byte write enable signals,  $\overline{BWE}$ ,  $\overline{GW}$  = H.
- 8. The DQ pins are controlled by the current cycle and the  $\overline{OE}$  signal.  $\overline{OE}$  is asynchronous and is not sampled with the clock.
- 9.  $\overline{CE}_1$ , CE<sub>2</sub>, and  $\overline{CE}_3$  are available only in the TQFP package. BGA package has only two chip selects  $\overline{CE}_1$  and CE<sub>2</sub>.
- 10. The SRAM always initiates a read cycle when ADSP is asserted, regardless of the state of  $\overline{GW}$ , BWE, or  $\overline{BW}_x$ . Writes may occur only on subsequent clocks after the ADSP or with the assertion of ADSC. As a result,  $\overline{OE}$  must be driven HIGH prior to the start of the Write cycle to allow the outputs to tri-state.  $\overline{OE}$  is a don't care for the remainder of the write cycle.
- 11.  $\overline{OE}$  is asynchronous and is not sampled with the clock rise. It is masked internally during write cycles. During a read cycle all data bits are tri-State when  $\overline{OE}$  is inactive or when the device is deselected, and all data bits behave as output when  $\overline{OE}$  is active (LOW).

### Partial Truth Table for Read/Write

The Partial Truth Table for Read/Write follows.<sup>[12, 13]</sup>

Function (CY7C1360C)	$\overline{GW}$	$\overline{BWE}$	$\overline{BW}_D$	$\overline{BW}_C$	$\overline{BW}_B$	$\overline{BW}_A$
Read	H	H	X	X	X	X
Read	H	L	H	H	H	H
Write byte A – (DQ <sub>A</sub> and DQP <sub>A</sub> )	H	L	H	H	H	L
Write byte B – (DQ <sub>B</sub> and DQP <sub>B</sub> )	H	L	H	H	L	H
Write bytes B, A	H	L	H	H	L	L
Write byte C – (DQ <sub>C</sub> and DQP <sub>C</sub> )	H	L	H	L	H	H
Write bytes C, A	H	L	H	L	H	L
Write bytes C, B	H	L	H	L	L	H
Write bytes C, B, A	H	L	H	L	L	L
Write byte D – (DQ <sub>D</sub> and DQP <sub>D</sub> )	H	L	L	H	H	H
Write bytes D, A	H	L	L	H	H	L
Write bytes D, B	H	L	L	H	L	H
Write bytes D, B, A	H	L	L	H	L	L
Write bytes D, C	H	L	L	L	H	H
Write bytes D, C, A	H	L	L	L	H	L
Write bytes D, C, B	H	L	L	L	L	H
Write all bytes	H	L	L	L	L	L
Write all bytes	L	X	X	X	X	X

### Truth Table for Read/Write

The Truth Table for Read/Write follows.<sup>[12, 13]</sup>

Function (CY7C1362C)	$\overline{GW}$	$\overline{BWE}$	$\overline{BW}_B$	$\overline{BW}_A$
Read	H	H	X	X
Read	H	L	H	H
Write byte A – (DQ <sub>A</sub> and DQP <sub>A</sub> )	H	L	H	L
Write byte B – (DQ <sub>B</sub> and DQP <sub>B</sub> )	H	L	L	H
Write bytes B, A	H	L	L	L
Write all bytes	H	L	L	L
Write all bytes	L	X	X	X

#### Notes

12. The DQ pins are controlled by the current cycle and the  $\overline{OE}$  signal.  $\overline{OE}$  is asynchronous and is not sampled with the clock.

13. Table only lists a partial listing of the byte write combinations. Any combination of  $\overline{BW}_x$  is valid. Appropriate write will be done based on which byte write is active.

### IEEE 1149.1 Serial Boundary Scan (JTAG)

The CY7C1360C/CY7C1362C incorporates a serial boundary scan test access port (TAP) in the BGA package only. The TQFP package does not offer this functionality. This part operates in accordance with IEEE Standard 1149.1-1900, but does not have the set of functions required for full 1149.1 compliance. These functions from the IEEE specification are excluded because their inclusion places an added delay in the critical speed path of the SRAM. Note that the TAP controller functions in a manner that does not conflict with the operation of other devices using 1149.1 fully compliant TAPs. The TAP operates using JEDEC-standard 3.3 V or 2.5 V I/O logic levels.

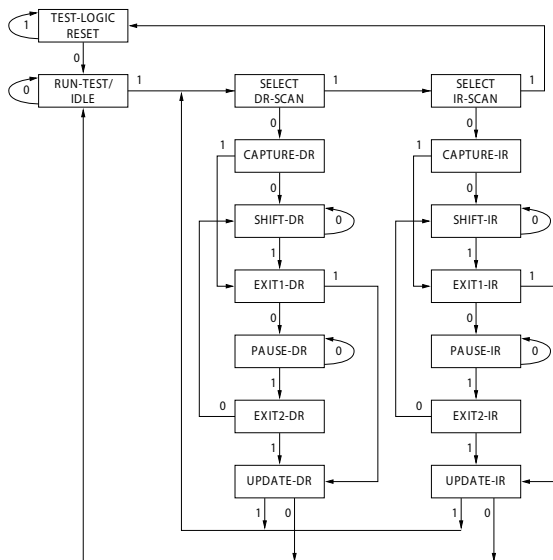
The CY7C1360C/CY7C1362C contains a TAP controller, instruction register, boundary scan register, bypass register, and ID register.

### Disabling the JTAG Feature

It is possible to operate the SRAM without using the JTAG feature. To disable the TAP controller, TCK must be tied LOW ( $V_{SS}$ ) to prevent clocking of the device. TDI and TMS are internally pulled up and may be unconnected. They may alternately be connected to  $V_{DD}$  through a pull-up resistor. TDO should be left unconnected. Upon power-up, the device comes up in a reset state which does not interfere with the operation of the device.

### TAP Controller State Diagram

The 0/1 next to each state represents the value of TMS at the rising edge of TCK.



### Test Access Port (TAP)

#### Test Clock (TCK)

The test clock is used only with the TAP controller. All inputs are captured on the rising edge of TCK. All outputs are driven from the falling edge of TCK.

#### Test Mode Select (TMS)

The TMS input is used to give commands to the TAP controller and is sampled on the rising edge of TCK. It is allowable to leave this ball unconnected if the TAP is not used. The ball is pulled up internally, resulting in a logic HIGH level.

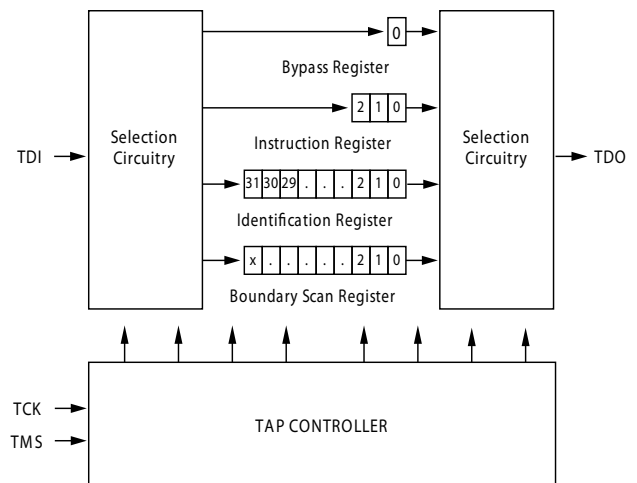
#### Test Data-In (TDI)

The TDI ball is used to serially input information into the registers and can be connected to the input of any of the registers. The register between TDI and TDO is chosen by the instruction that is loaded into the TAP instruction register. For information on loading the instruction register, see [TAP Controller State Diagram](#). TDI is internally pulled up and can be unconnected if the TAP is unused in an application. TDI is connected to the most significant bit (MSB) of any register. (See [TAP Controller Block Diagram](#).)

#### Test Data-Out (TDO)

The TDO output ball is used to serially clock data-out from the registers. The output is active depending upon the current state of the TAP state machine. The output changes on the falling edge of TCK. TDO is connected to the least significant bit (LSB) of any register. (See [TAP Controller State Diagram](#).)

### TAP Controller Block Diagram



## Performing a TAP Reset

A RESET is performed by forcing TMS HIGH ( $V_{DD}$ ) for five rising edges of TCK. This RESET does not affect the operation of the SRAM and may be performed while the SRAM is operating.

At power-up, the TAP is reset internally to ensure that TDO comes up in a high Z state.

## TAP Registers

Registers are connected between the TDI and TDO balls and enable data to be scanned into and out of the SRAM test circuitry. Only one register can be selected at a time through the instruction register. Data is serially loaded into the TDI ball on the rising edge of TCK. Data is output on the TDO ball on the falling edge of TCK.

### Instruction Register

Three-bit instructions can be serially loaded into the instruction register. This register is loaded when it is placed between the TDI and TDO balls as shown in the [TAP Controller Block Diagram on page 13](#). Upon power-up, the instruction register is loaded with the IDCODE instruction. It is also loaded with the IDCODE instruction if the controller is placed in a reset state as described in the previous section.

When the TAP controller is in the Capture-IR state, the two least significant bits are loaded with a binary "01" pattern to enable fault isolation of the board-level serial test data path.

### Bypass Register

To save time when serially shifting data through registers, it is sometimes advantageous to skip certain chips. The bypass register is a single-bit register that can be placed between the TDI and TDO balls. This enables data to be shifted through the SRAM with minimal delay. The bypass register is set LOW ( $V_{SS}$ ) when the BYPASS instruction is executed.

### Boundary Scan Register

The boundary scan register is connected to all the input and bidirectional balls on the SRAM.

The boundary scan register is loaded with the contents of the RAM I/O ring when the TAP controller is in the Capture-DR state and is then placed between the TDI and TDO balls when the controller is moved to the Shift-DR state. The EXTEST, SAMPLE/PRELOAD and SAMPLE Z instructions can be used to capture the contents of the I/O ring.

The Boundary Scan Order tables ([165-ball FBGA Boundary Scan Order on page 19](#) and [119-ball BGA Boundary Scan Order on page 20](#)) show the order in which the bits are connected. Each bit corresponds to one of the bumps on the SRAM package. The MSB of the register is connected to TDI and the LSB is connected to TDO.

### Identification (ID) Register

The ID register is loaded with a vendor-specific, 32-bit code during the Capture-DR state when the IDCODE command is loaded in the instruction register. The IDCODE is hardwired into the SRAM and can be shifted out when the TAP controller is in the Shift-DR state. The ID register has a vendor code and other information described in [Identification Register Definitions on page 18](#).

## TAP Instruction Set

### Overview

Eight different instructions are possible with the three-bit instruction register. All combinations are listed in [Identification Codes on page 18](#). Three of these instructions are listed as RESERVED and should not be used. The other five instructions are described in detail in this section.

The TAP controller used in this SRAM is not fully compliant to the 1149.1 convention because some of the mandatory 1149.1 instructions are not fully implemented.

The TAP controller cannot be used to load address data or control signals into the SRAM and cannot preload the I/O buffers. The SRAM does not implement the 1149.1 commands EXTEST or INTEST or the PRELOAD portion of SAMPLE/PRELOAD; rather, it performs a capture of the I/O ring when these instructions are executed.

Instructions are loaded into the TAP controller during the Shift-IR state when the instruction register is placed between TDI and TDO. During this state, instructions are shifted through the instruction register through the TDI and TDO balls. To execute the instruction once it is shifted in, the TAP controller needs to be moved into the Update-IR state.

### EXTEST

EXTEST is a mandatory 1149.1 instruction which is to be executed whenever the instruction register is loaded with all 0s. EXTEST is not implemented in this SRAM TAP controller, and therefore this device is not compliant to 1149.1. The TAP controller does recognize an all-0 instruction.

When an EXTEST instruction is loaded into the instruction register, the SRAM responds as if a SAMPLE/PRELOAD instruction has been loaded. There is one difference between the two instructions. Unlike the SAMPLE/PRELOAD instruction, EXTEST places the SRAM outputs in a high Z state.

### IDCODE

The IDCODE instruction causes a vendor-specific, 32-bit code to be loaded into the instruction register. It also places the instruction register between the TDI and TDO balls and allows the IDCODE to be shifted out of the device when the TAP controller enters the Shift-DR state.

The IDCODE instruction is loaded into the instruction register upon power up or whenever the TAP controller is given a test logic reset state.

### SAMPLE Z

The SAMPLE Z instruction causes the boundary scan register to be connected between the TDI and TDO balls when the TAP controller is in a Shift-DR state. It also places all SRAM outputs into a high Z state.

### SAMPLE/PRELOAD

SAMPLE/PRELOAD is a 1149.1 mandatory instruction. When the SAMPLE/PRELOAD instructions are loaded into the instruction register and the TAP controller is in the Capture-DR state, a snapshot of data on the inputs and output pins is captured in the boundary scan register.



The user must be aware that the TAP controller clock can only operate at a frequency up to 20 MHz, while the SRAM clock operates more than an order of magnitude faster. Because there is a large difference in the clock frequencies, it is possible that during the Capture-DR state, an input or output will undergo a transition. The TAP may then try to capture a signal while in transition (metastable state). This will not harm the device, but there is no guarantee as to the value that will be captured. Repeatable results may not be possible.

To guarantee that the boundary scan register will capture the correct value of a signal, the SRAM signal must be stabilized long enough to meet the TAP controller's capture setup plus hold times ( $t_{CS}$  and  $t_{CH}$ ). The SRAM clock input might not be captured correctly if there is no way in a design to stop (or slow) the clock during a SAMPLE/PRELOAD instruction. If this is an issue, it is still possible to capture all other signals and simply ignore the value of the CK and CK captured in the boundary scan register.

After the data is captured, it is possible to shift out the data by putting the TAP into the Shift-DR state. This places the boundary scan register between the TDI and TDO pins.

PRELOAD enables an initial data pattern to be placed at the latched parallel outputs of the boundary scan register cells prior to the selection of another boundary scan test operation.

The shifting of data for the SAMPLE and PRELOAD phases can occur concurrently when required - that is, while data captured is shifted out, the preloaded data can be shifted in.

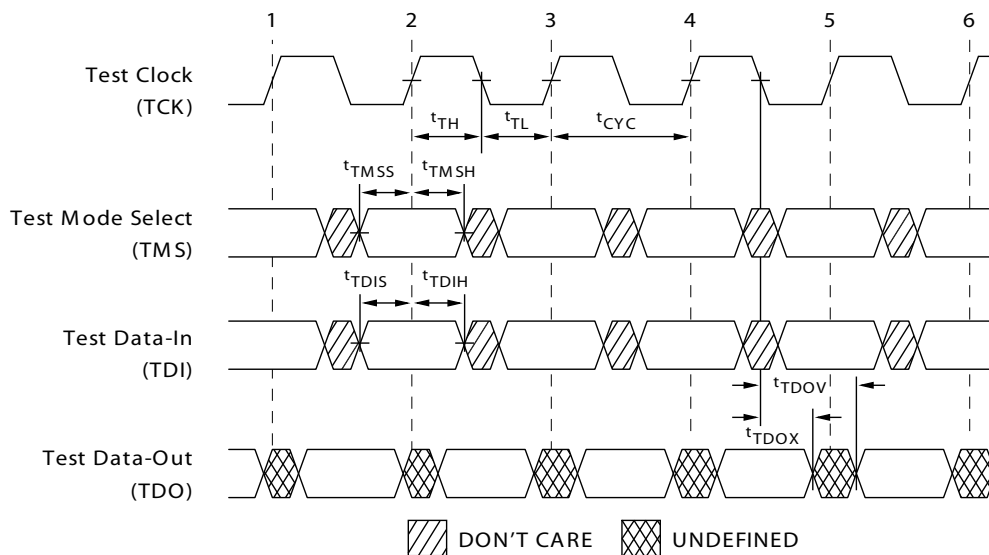
**BYPASS**

When the BYPASS instruction is loaded in the instruction register and the TAP is placed in a Shift-DR state, the bypass register is placed between the TDI and TDO balls. The advantage of the BYPASS instruction is that it shortens the boundary scan path when multiple devices are connected together on a board.

**Reserved**

These instructions are not implemented but are reserved for future use. Do not use these instructions.

**TAP Timing**



## TAP AC Switching Characteristics

Over the Operating Range<sup>[14, 15]</sup>

Parameter	Description	Min	Max	Unit
<b>Clock</b>				
$t_{TCYC}$	TCK clock cycle time	50	–	ns
$t_{TF}$	TCK clock frequency	–	20	MHz
$t_{TH}$	TCK clock HIGH time	20	–	ns
$t_{TL}$	TCK clock LOW time	20	–	ns
<b>Output Times</b>				
$t_{TDOV}$	TCK clock LOW to TDO valid	–	10	ns
$t_{TDOX}$	TCK clock LOW to TDO invalid	0	–	ns
<b>Setup Times</b>				
$t_{TMSS}$	TMS setup to TCK clock rise	5	–	ns
$t_{TDIS}$	TDI setup to TCK clock rise	5	–	ns
$t_{CS}$	Capture setup to TCK rise	5	–	ns
<b>Hold Times</b>				
$t_{TMSH}$	TMS hold after TCK clock rise	5	–	ns
$t_{TDIH}$	TDI hold after clock rise	5	–	ns
$t_{CH}$	Capture hold after clock rise	5	–	ns

### Notes

14.  $t_{CS}$  and  $t_{CH}$  refer to the setup and hold time requirements of latching data from the boundary scan register.  
 15. Test conditions are specified using the load in TAP AC test Conditions.  $t_R/t_F = 1$  ns.



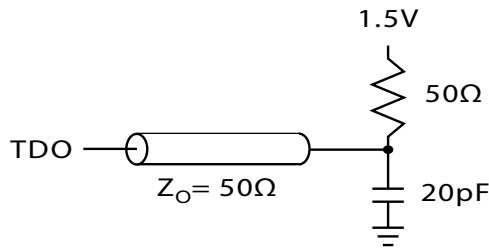
### 3.3 V TAP AC Test Conditions

Input pulse levels.....  $V_{SS}$  to 3.3 V  
 Input rise and fall times..... 1 ns  
 Input timing reference levels..... 1.5 V  
 Output reference levels ..... 1.5 V  
 Test load termination supply voltage ..... 1.5 V

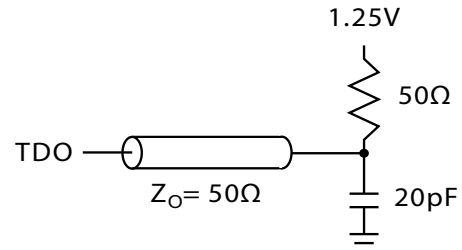
### 2.5 V TAP AC Test Conditions

Input pulse levels.....  $V_{SS}$  to 2.5 V  
 Input rise and fall time ..... 1 ns  
 Input timing reference levels..... 1.25 V  
 Output reference levels ..... 1.25 V  
 Test load termination supply voltage ..... 1.25 V

### 3.3 V TAP AC Output Load Equivalent



### 2.5 V TAP AC Output Load Equivalent



## TAP DC Electrical Characteristics and Operating Conditions

(0 °C <  $T_A$  < +70 °C;  $V_{DD} = 3.3 \text{ V} \pm 0.165 \text{ V}$  unless otherwise noted)<sup>[16]</sup>

Parameter	Description	Conditions		Min	Max	Unit
$V_{OH1}$	Output HIGH voltage	$I_{OH} = -4.0 \text{ mA}$	$V_{DDQ} = 3.3 \text{ V}$	2.4	–	V
		$I_{OH} = -1.0 \text{ mA}$	$V_{DDQ} = 2.5 \text{ V}$	2.0	–	V
$V_{OH2}$	Output HIGH voltage	$I_{OH} = -100 \mu\text{A}$	$V_{DDQ} = 3.3 \text{ V}$	2.9	–	V
			$V_{DDQ} = 2.5 \text{ V}$	2.1	–	V
$V_{OL1}$	Output LOW voltage	$I_{OL} = 8.0 \text{ mA}$	$V_{DDQ} = 3.3 \text{ V}$	–	0.4	V
			$V_{DDQ} = 2.5 \text{ V}$	–	0.4	V
$V_{OL2}$	Output LOW voltage	$I_{OL} = 100 \mu\text{A}$	$V_{DDQ} = 3.3 \text{ V}$	–	0.2	V
			$V_{DDQ} = 2.5 \text{ V}$	–	0.2	V
$V_{IH}$	Input HIGH voltage		$V_{DDQ} = 3.3 \text{ V}$	2.0	$V_{DD} + 0.3$	V
			$V_{DDQ} = 2.5 \text{ V}$	1.7	$V_{DD} + 0.3$	V
$V_{IL}$	Input LOW voltage		$V_{DDQ} = 3.3 \text{ V}$	–0.5	0.7	V
			$V_{DDQ} = 2.5 \text{ V}$	–0.3	0.7	V
$I_X$	Input load current	$\text{GND} \leq V_{IN} \leq V_{DDQ}$		–5	5	$\mu\text{A}$

**Note**

16. All voltages referenced to  $V_{SS}$  (GND)

### Identification Register Definitions

Instruction Field	CY7C1360C (256KX36)	CY7C1362C (512KX18)	Description
Revision number (31:29)	000	000	Describes the version number
Device depth (28:24) <sup>[17]</sup>	01011	01011	Reserved for internal use
Device width (23:18) 119-BGA	101000	101000	Defines memory type and architecture
Device width (23:18) 165- FBGA	000000	000000	Defines memory type and architecture
Cypress device ID (17:12)	100110	010110	Defines width and density
Cypress JEDEC ID code (11:1)	00000110100	00000110100	Allows unique identification of SRAM vendor
ID register presence indicator (0)	1	1	Indicates the presence of an ID register

### Scan Register Sizes

Register Name	Bit Size (× 36)	Bit Size (× 18)
Instruction	3	3
Bypass	1	1
ID	32	32
Boundary scan order (119-ball BGA package)	71	71
Boundary scan order (165-ball FBGA package)	71	71

### Identification Codes

Instruction	Code	Description
EXTTEST	000	Captures I/O ring contents. Places the boundary scan register between TDI and TDO. Forces all SRAM outputs to high Z state.
IDCODE	001	Loads the ID register with the vendor ID code and places the register between TDI and TDO. This operation does not affect SRAM operations.
SAMPLE Z	010	Captures I/O ring contents. Places the boundary scan register between TDI and TDO. Forces all SRAM output drivers to a high Z state.
RESERVED	011	Do Not Use: This instruction is reserved for future use.
SAMPLE/PRELOAD	100	Captures I/O ring contents. Places the boundary scan register between TDI and TDO. Does not affect SRAM operation.
RESERVED	101	Do Not Use: This instruction is reserved for future use.
RESERVED	110	Do Not Use: This instruction is reserved for future use.
BYPASS	111	Places the bypass register between TDI and TDO. This operation does not affect SRAM operations.

**Note**

<sup>17</sup>. Bit #24 is "1" in the Register Definitions for both 2.5 V and 3.3 V versions of this device.

**165-ball FBGA Boundary Scan Order**

CY7C1360C (256 K × 36)					
Bit#	Ball ID	Signal Name	Bit#	Ball ID	Signal Name
1	B6	CLK	37	R6	A0
2	B7	$\overline{\text{GW}}$	38	P6	A1
3	A7	$\overline{\text{BWE}}$	39	R4	A
4	B8	$\overline{\text{OE}}$	40	P4	A
5	A8	$\overline{\text{ADSC}}$	41	R3	A
6	B9	$\overline{\text{ADSP}}$	42	P3	A
7	A9	$\overline{\text{ADV}}$	43	R1	MODE
8	B10	A	44	N1	DQP <sub>D</sub>
9	A10	A	45	L2	DQ <sub>D</sub>
10	C11	DQP <sub>B</sub>	46	K2	DQ <sub>D</sub>
11	E10	DQ <sub>B</sub>	47	J2	DQ <sub>D</sub>
12	F10	DQ <sub>B</sub>	48	M2	DQ <sub>D</sub>
13	G10	DQ <sub>B</sub>	49	M1	DQ <sub>D</sub>
14	D10	DQ <sub>B</sub>	50	L1	DQ <sub>D</sub>
15	D11	DQ <sub>B</sub>	51	K1	DQ <sub>D</sub>
16	E11	DQ <sub>B</sub>	52	J1	DQ <sub>D</sub>
17	F11	DQ <sub>B</sub>	53	Internal	Internal
18	G11	DQ <sub>B</sub>	54	G2	DQ <sub>C</sub>
19	H11	ZZ	55	F2	DQ <sub>C</sub>
20	J10	DQ <sub>A</sub>	56	E2	DQ <sub>C</sub>
21	K10	DQ <sub>A</sub>	57	D2	DQ <sub>C</sub>
22	L10	DQ <sub>A</sub>	58	G1	DQ <sub>C</sub>
23	M10	DQ <sub>A</sub>	59	F1	DQ <sub>C</sub>
24	J11	DQ <sub>A</sub>	60	E1	DQ <sub>C</sub>
25	K11	DQ <sub>A</sub>	61	D1	DQ <sub>C</sub>
26	L11	DQ <sub>A</sub>	62	C1	DQP <sub>C</sub>
27	M11	DQ <sub>A</sub>	63	B2	A
28	N11	DQP <sub>A</sub>	64	A2	A
29	R11	A	65	A3	CE <sub>1</sub>
30	R10	A	66	B3	CE <sub>2</sub>
31	P10	A	67	B4	$\overline{\text{BW}}_{\text{D}}$
32	R9	A	68	A4	$\overline{\text{BW}}_{\text{C}}$
33	P9	A	69	A5	$\overline{\text{BW}}_{\text{B}}$
34	R8	A	70	B5	$\overline{\text{BW}}_{\text{A}}$
35	P8	A	71	A6	$\overline{\text{CE}}_{\text{3}}$
36	P11	A			

CY7C1362C (512 K × 18)					
Bit#	ball ID	Signal Name	Bit#	ball ID	Signal Name
1	B6	CLK	37	R6	A0
2	B7	$\overline{\text{GW}}$	38	P6	A1
3	A7	$\overline{\text{BWE}}$	39	R4	A
4	B8	$\overline{\text{OE}}$	40	P4	A
5	A8	$\overline{\text{ADSC}}$	41	R3	A
6	B9	$\overline{\text{ADSP}}$	42	P3	A
7	A9	$\overline{\text{ADV}}$	43	R1	MODE
8	B10	A	44	Internal	Internal
9	A10	A	45	Internal	Internal
10	A11	A	46	Internal	Internal
11	Internal	Internal	47	Internal	Internal
12	Internal	Internal	48	N1	DQP <sub>B</sub>
13	Internal	Internal	49	M1	DQ <sub>B</sub>
14	C11	DQP <sub>A</sub>	50	L1	DQ <sub>B</sub>
15	D11	DQ <sub>A</sub>	51	K1	DQ <sub>B</sub>
16	E11	DQ <sub>A</sub>	52	J1	DQ <sub>B</sub>
17	F11	DQ <sub>A</sub>	53	Internal	Internal
18	G11	DQ <sub>A</sub>	54	G2	DQ <sub>B</sub>
19	H11	ZZ	55	F2	DQ <sub>B</sub>
20	J10	DQ <sub>A</sub>	56	E2	DQ <sub>B</sub>
21	K10	DQ <sub>A</sub>	57	D2	DQ <sub>B</sub>
22	L10	DQ <sub>A</sub>	58	Internal	Internal
23	M10	DQ <sub>A</sub>	59	Internal	Internal
24	Internal	Internal	60	Internal	Internal
25	Internal	Internal	61	Internal	Internal
26	Internal	Internal	62	Internal	Internal
27	Internal	Internal	63	B2	A
28	Internal	Internal	64	A2	A
29	R11	A	65	A3	CE <sub>1</sub>
30	R10	A	66	B3	CE <sub>2</sub>
31	P10	A	67	Internal	Internal
32	R9	A	68	Internal	Internal
33	P9	A	69	A4	$\overline{\text{BW}}_{\text{B}}$
34	R8	A	70	B5	$\overline{\text{BW}}_{\text{A}}$
35	P8	A	71	A6	$\overline{\text{CE}}_{\text{3}}$
36	P11	A			

**119-ball BGA Boundary Scan Order**

CY7C1360C (256 K × 36)					
Bit#	ball ID	Signal Name	Bit#	ball ID	Signal Name
1	K4	CLK	37	P4	A0
2	H4	$\overline{GW}$	38	N4	A1
3	M4	$\overline{BWE}$	39	R6	A
4	F4	$\overline{OE}$	40	T5	A
5	B4	$\overline{ADSC}$	41	T3	A
6	A4	$\overline{ADSP}$	42	R2	A
7	G4	$\overline{ADV}$	43	R3	MODE
8	C3	A	44	P2	DQP <sub>D</sub>
9	B3	A	45	P1	DQ <sub>D</sub>
10	D6	DQP <sub>B</sub>	46	L2	DQ <sub>D</sub>
11	H7	DQ <sub>B</sub>	47	K1	DQ <sub>D</sub>
12	G6	DQ <sub>B</sub>	48	N2	DQ <sub>D</sub>
13	E6	DQ <sub>B</sub>	49	N1	DQ <sub>D</sub>
14	D7	DQ <sub>B</sub>	50	M2	DQ <sub>D</sub>
15	E7	DQ <sub>B</sub>	51	L1	DQ <sub>D</sub>
16	F6	DQ <sub>B</sub>	52	K2	DQ <sub>D</sub>
17	G7	DQ <sub>B</sub>	53	Internal	Internal
18	H6	DQ <sub>B</sub>	54	H1	DQ <sub>C</sub>
19	T7	ZZ	55	G2	DQ <sub>C</sub>
20	K7	DQ <sub>A</sub>	56	E2	DQ <sub>C</sub>
21	L6	DQ <sub>A</sub>	57	D1	DQ <sub>C</sub>
22	N6	DQ <sub>A</sub>	58	H2	DQ <sub>C</sub>
23	P7	DQ <sub>A</sub>	59	G1	DQ <sub>C</sub>
24	N7	DQ <sub>A</sub>	60	F2	DQ <sub>C</sub>
25	M6	DQ <sub>A</sub>	61	E1	DQ <sub>C</sub>
26	L7	DQ <sub>A</sub>	62	D2	DQP <sub>C</sub>
27	K6	DQ <sub>A</sub>	63	C2	A
28	P6	DQP <sub>A</sub>	64	A2	A
29	T4	A	65	E4	$\overline{CE}_1$
30	A3	A	66	B2	$CE_2$
31	C5	A	67	L3	$\overline{BWD}$
32	B5	A	68	G3	$\overline{BW}_C$
33	A5	A	69	G5	$\overline{BW}_B$
34	C6	A	70	L5	$\overline{BW}_A$
35	A6	A	71	Internal	Internal
36	B6	A			

CY7C1362C (512 K × 18)					
Bit#	ball ID	Signal Name	Bit#	ball ID	Signal Name
1	K4	CLK	37	P4	A0
2	H4	$\overline{GW}$	38	N4	A1
3	M4	$\overline{BWE}$	39	R6	A
4	F4	$\overline{OE}$	40	T5	A
5	B4	$\overline{ADSC}$	41	T3	A
6	A4	$\overline{ADSP}$	42	R2	A
7	G4	$\overline{ADV}$	43	R3	MODE
8	C3	A	44	Internal	Internal
9	B3	A	45	Internal	Internal
10	T2	A	46	Internal	Internal
11	Internal	Internal	47	Internal	Internal
12	Internal	Internal	48	P2	DQP <sub>B</sub>
13	Internal	Internal	49	N1	DQ <sub>B</sub>
14	D6	DQP <sub>A</sub>	50	M2	DQ <sub>B</sub>
15	E7	DQ <sub>A</sub>	51	L1	DQ <sub>B</sub>
16	F6	DQ <sub>A</sub>	52	K2	DQ <sub>B</sub>
17	G7	DQ <sub>A</sub>	53	Internal	Internal
18	H6	DQ <sub>A</sub>	54	H1	DQ <sub>B</sub>
19	T7	ZZ	55	G2	DQ <sub>B</sub>
20	K7	DQ <sub>A</sub>	56	E2	DQ <sub>B</sub>
21	L6	DQ <sub>A</sub>	57	D1	DQ <sub>B</sub>
22	N6	DQ <sub>A</sub>	58	Internal	Internal
23	P7	DQ <sub>A</sub>	59	Internal	Internal
24	Internal	Internal	60	Internal	Internal
25	Internal	Internal	61	Internal	Internal
26	Internal	Internal	62	Internal	Internal
27	Internal	Internal	63	C2	A
28	Internal	Internal	64	A2	A
29	T6	A	65	E4	$\overline{CE}_1$
30	A3	A	66	B2	$CE_2$
31	C5	A	67	Internal	Internal
32	B5	A	68	Internal	Internal
33	A5	A	69	G3	$\overline{BW}_B$
34	C6	A	70	L5	$\overline{BW}_A$
35	A6	A	71	Internal	Internal
36	B6	A			

## Maximum Ratings

Exceeding maximum ratings may impair the useful life of the device. These user guidelines are not tested.

Storage temperature ..... -65 °C to +150 °C  
 Ambient temperature with power applied ..... -55 °C to +125 °C  
 Supply voltage on V<sub>DD</sub> relative to GND ..... -0.5 V to +4.6 V  
 Supply voltage on V<sub>DDQ</sub> relative to GND ..... -0.5 V to +V<sub>DD</sub>  
 DC voltage applied to outputs in tri-state ..... -0.5 V to V<sub>DDQ</sub> + 0.5 V  
 DC input voltage ..... -0.5 V to V<sub>DD</sub> + 0.5 V  
 Current into outputs (LOW) ..... 20 mA  
 Static discharge voltage ..... > 2001 V (per MIL-STD-883, method 3015)  
 Latch-up current ..... > 200 mA

## Neutron Soft Error Immunity

Parameter	Description	Test Conditions	Typ	Max*	Unit
LSBU	Logical single-bit upsets	25 °C	361	394	FIT/Mb
LMBU	Logical multi-bit upsets	25 °C	0	0.01	FIT/Mb
SEL	Single event latch-up	85 °C	0	0.1	FIT/Dev

\* No LMBU or SEL events occurred during testing; this column represents a statistical  $\chi^2$ , 95% confidence limit calculation. For more details refer to Application Note AN54908 "Accelerated Neutron SER Testing and Calculation of Terrestrial Failure Rates"

## Operating Range

Range	Ambient Temperature	V <sub>DD</sub>	V <sub>DDQ</sub>
Commercial	0 °C to +70 °C	3.3 V – 5 % / + 10%	2.5 V – 5% to V <sub>DD</sub>
Industrial	-40 °C to +85 °C		

## Electrical Characteristics

Over the Operating Range<sup>[18, 19]</sup>

Parameter	Description	Test Conditions	Min	Max	Unit
V <sub>DD</sub>	Power supply voltage		3.135	3.6	V
V <sub>DDQ</sub>	I/O supply voltage	for 3.3 V I/O	3.135	V <sub>DD</sub>	V
		for 2.5 V I/O	2.375	2.625	V
V <sub>OH</sub>	Output HIGH voltage	for 3.3 V I/O, I <sub>OH</sub> = -4.0 mA	2.4	-	V
		for 2.5 V I/O, I <sub>OH</sub> = -1.0 mA	2.0	-	V
V <sub>OL</sub>	Output LOW voltage	for 3.3 V I/O, I <sub>OL</sub> = 8.0 mA	-	0.4	V
		for 2.5 V I/O, I <sub>OL</sub> = 1.0 mA	-	0.4	V
V <sub>IH</sub>	Input HIGH voltage <sup>[18]</sup>	for 3.3 V I/O	2.0	V <sub>DD</sub> + 0.3 V	V
		for 2.5 V I/O	1.7	V <sub>DD</sub> + 0.3 V	V
V <sub>IL</sub>	Input LOW voltage <sup>[18]</sup>	for 3.3 V I/O	-0.3	0.8	V
		for 2.5 V I/O	-0.3	0.7	V
I <sub>X</sub>	Input leakage current except ZZ and MODE	GND ≤ V <sub>I</sub> ≤ V <sub>DDQ</sub>	-5	5	μA
		Input = V <sub>SS</sub>	-30	-	μA
		Input = V <sub>DD</sub>	-	5	μA
		Input = V <sub>SS</sub>	-5	-	μA
I <sub>OZ</sub>	Output leakage current	Input = V <sub>DD</sub>	-	30	μA
		GND ≤ V <sub>I</sub> ≤ V <sub>DDQ</sub> , output disabled	-5	5	μA

### Notes

18. Overshoot: V<sub>IH</sub>(AC) < V<sub>DD</sub> + 1.5 V (Pulse width less than t<sub>CYC/2</sub>), undershoot: V<sub>IL</sub>(AC) > -2 V (Pulse width less than t<sub>CYC/2</sub>).  
 19. T<sub>Power-up</sub>: Assumes a linear ramp from 0 V to V<sub>DD</sub>(min) within 200 ms. During this time V<sub>IH</sub> < V<sub>DD</sub> and V<sub>DDQ</sub> ≤ V<sub>DD</sub>.

**Electrical Characteristics** (continued)

 Over the Operating Range<sup>[18, 19]</sup>

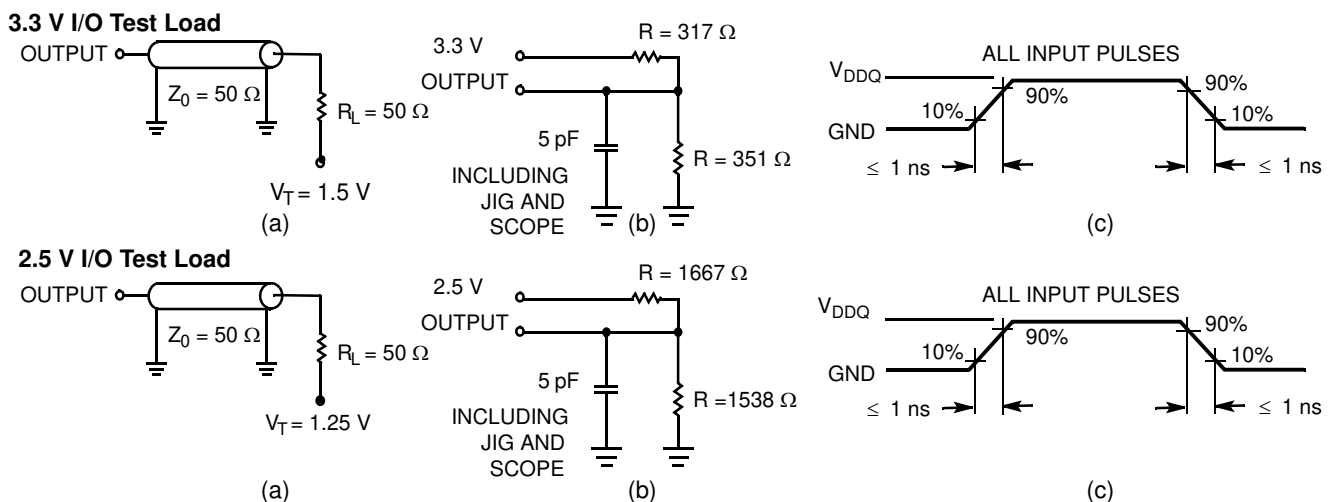
Parameter	Description	Test Conditions	Min	Max	Unit	
$I_{DD}$	$V_{DD}$ operating supply current	$V_{DD} = \text{Max}$ , $I_{OUT} = 0 \text{ mA}$ , $f = f_{MAX} = 1/t_{CYC}$	4 ns cycle, 250 MHz	–	250	mA
			5 ns cycle, 200 MHz	–	220	mA
			6 ns cycle, 166 MHz	–	180	mA
$I_{SB1}$	Automatic CE power-down current—TTL inputs	$V_{DD} = \text{Max}$ , device deselected, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$ , $f = f_{MAX} = 1/t_{CYC}$	4 ns cycle, 250 MHz	–	130	mA
			5 ns cycle, 200 MHz	–	120	mA
			6 ns cycle, 166 MHz	–	110	mA
$I_{SB2}$	Automatic CE power-down current—CMOS inputs	$V_{DD} = \text{Max}$ , device deselected, $V_{IN} \leq 0.3 \text{ V}$ or $V_{IN} \geq V_{DDQ} - 0.3 \text{ V}$ , $f = 0$	All speeds	–	40	mA
$I_{SB3}$	Automatic CE power-down current—CMOS inputs	$V_{DD} = \text{Max}$ , device deselected, or $V_{IN} \leq 0.3 \text{ V}$ or $V_{IN} \geq V_{DDQ} - 0.3 \text{ V}$ , $f = f_{MAX} = 1/t_{CYC}$	4 ns cycle, 250 MHz	–	120	mA
			5 ns cycle, 200 MHz	–	110	mA
			6 ns cycle, 166 MHz	–	100	mA
$I_{SB4}$	Automatic CE power-down current—TTL inputs	$V_{DD} = \text{Max}$ , device deselected, $V_{IN} \geq V_{IH}$ or $V_{IN} \leq V_{IL}$ , $f = 0$	All speeds	–	40	mA

**Capacitance**<sup>[20]</sup>

Parameter	Description	Test Conditions	100 TQFP Max	119 BGA Max	165 FBGA Max	Unit
$C_{IN}$	Input capacitance	$T_A = 25 \text{ }^\circ\text{C}$ , $f = 1 \text{ MHz}$ , $V_{DD} = 3.3 \text{ V}$ , $V_{DDQ} = 2.5 \text{ V}$	5	5	5	pF
$C_{CLK}$	Clock input capacitance		5	5	5	pF
$C_{I/O}$	Input/output capacitance		5	7	7	pF

**Thermal Resistance**<sup>[20]</sup>

Parameter	Description	Test Conditions	100 TQFP Package	119 BGA Package	165 FBGA Package	Unit
$\Theta_{JA}$	Thermal resistance (junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, according to EIA/JESD51.	29.41	34.1	16.8	$^\circ\text{C/W}$
$\Theta_{JC}$	Thermal resistance (junction to case)		6.13	14.0	3	$^\circ\text{C/W}$

**Figure 5. AC Test Loads and Waveforms**

**Note**

20. Tested initially and after any design or process change that may affect these parameters.

## Switching Characteristics

Over the Operating Range [21, 22]

Parameter	Description	-250		-200		-166		Unit
		Min	Max	Min	Max	Min	Max	
t <sub>POWER</sub>	V <sub>DD</sub> (Typical) to the first access <sup>[23]</sup>	1	–	1	–	1	–	ms
<b>Clock</b>								
t <sub>CYC</sub>	Clock cycle time	4.0	–	5.0	–	6.0	–	ns
t <sub>CH</sub>	Clock HIGH	1.8	–	2.0	–	2.4	–	ns
t <sub>CL</sub>	Clock LOW	1.8	–	2.0	–	2.4	–	ns
<b>Output Times</b>								
t <sub>CO</sub>	Data output valid after CLK rise	–	2.8	–	3.0	–	3.5	ns
t <sub>DOH</sub>	Data output hold after CLK rise	1.25	–	1.25	–	1.25	–	ns
t <sub>CLZ</sub>	Clock to low Z <sup>[24, 25, 26]</sup>	1.25	–	1.25	–	1.25	–	ns
t <sub>CHZ</sub>	Clock to high Z <sup>[24, 25, 26]</sup>	1.25	2.8	1.25	3.0	1.25	3.5	ns
t <sub>OEV</sub>	$\overline{OE}$ LOW to output valid	–	2.8	–	3.0	–	3.5	ns
t <sub>OELZ</sub>	$\overline{OE}$ LOW to output low Z <sup>[24, 25, 26]</sup>	0	–	0	–	0	–	ns
t <sub>OEHZ</sub>	$\overline{OE}$ HIGH to output high Z <sup>[24, 25, 26]</sup>	–	2.8	–	3.0	–	3.5	ns
<b>Set-up Times</b>								
t <sub>AS</sub>	Address setup before CLK rise	1.4	–	1.5	–	1.5	–	ns
t <sub>ADS</sub>	$\overline{ADSC}$ , $\overline{ADSP}$ setup before CLK rise	1.4	–	1.5	–	1.5	–	ns
t <sub>ADVS</sub>	$\overline{ADV}$ setup before CLK rise	1.4	–	1.5	–	1.5	–	ns
t <sub>WES</sub>	$\overline{GW}$ , $\overline{BWE}$ , $\overline{BW}_X$ setup before CLK rise	1.4	–	1.5	–	1.5	–	ns
t <sub>DS</sub>	Data input setup before CLK rise	1.4	–	1.5	–	1.5	–	ns
t <sub>CES</sub>	Chip enable setup before CLK rise	1.4	–	1.5	–	1.5	–	ns
<b>Hold Times</b>								
t <sub>AH</sub>	Address hold after CLK rise	0.4	–	0.5	–	0.5	–	ns
t <sub>ADH</sub>	$\overline{ADSP}$ , $\overline{ADSC}$ hold after CLK rise	0.4	–	0.5	–	0.5	–	ns
t <sub>ADVH</sub>	$\overline{ADV}$ hold after CLK rise	0.4	–	0.5	–	0.5	–	ns
t <sub>WEH</sub>	$\overline{GW}$ , $\overline{BWE}$ , $\overline{BW}_X$ hold after CLK rise	0.4	–	0.5	–	0.5	–	ns
t <sub>DH</sub>	Data input hold after CLK rise	0.4	–	0.5	–	0.5	–	ns
t <sub>CEH</sub>	Chip enable hold after CLK rise	0.4	–	0.5	–	0.5	–	ns

### Notes

21. Timing reference level is 1.5 V when V<sub>DDQ</sub> = 3.3 V and is 1.25 V when V<sub>DDQ</sub> = 2.5 V.

22. Test conditions shown in (a) of AC Test Loads unless otherwise noted.

23. This part has a voltage regulator internally; t<sub>POWER</sub> is the time that the power needs to be supplied above V<sub>DD</sub>(minimum) initially before a read or write operation can be initiated.

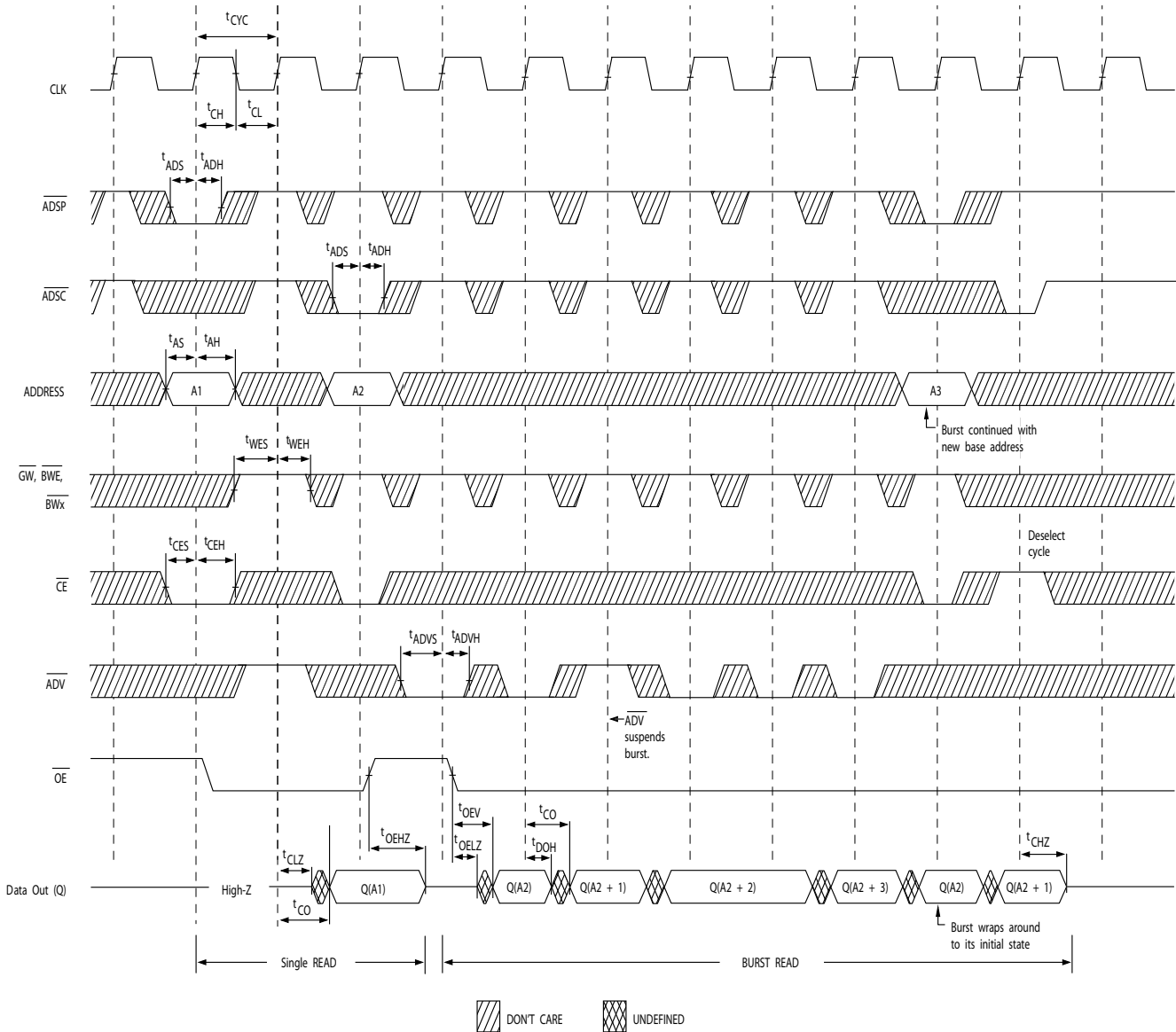
24. t<sub>CHZ</sub>, t<sub>CLZ</sub>, t<sub>OELZ</sub>, and t<sub>OEHZ</sub> are specified with AC test conditions shown in part (b) of AC Test Loads. Transition is measured ± 200 mV from steady-state voltage.

25. At any given voltage and temperature, t<sub>OEHZ</sub> is less than t<sub>OELZ</sub> and t<sub>CHZ</sub> is less than t<sub>CLZ</sub> to eliminate bus contention between SRAMs when sharing the same data bus. These specifications do not imply a bus contention condition, but reflect parameters guaranteed over worst case user conditions. Device is designed to achieve high Z prior to low Z under the same system conditions.

26. This parameter is sampled and not 100% tested.

## Switching Waveforms

Figure 6. Read Cycle Timing<sup>[27]</sup>



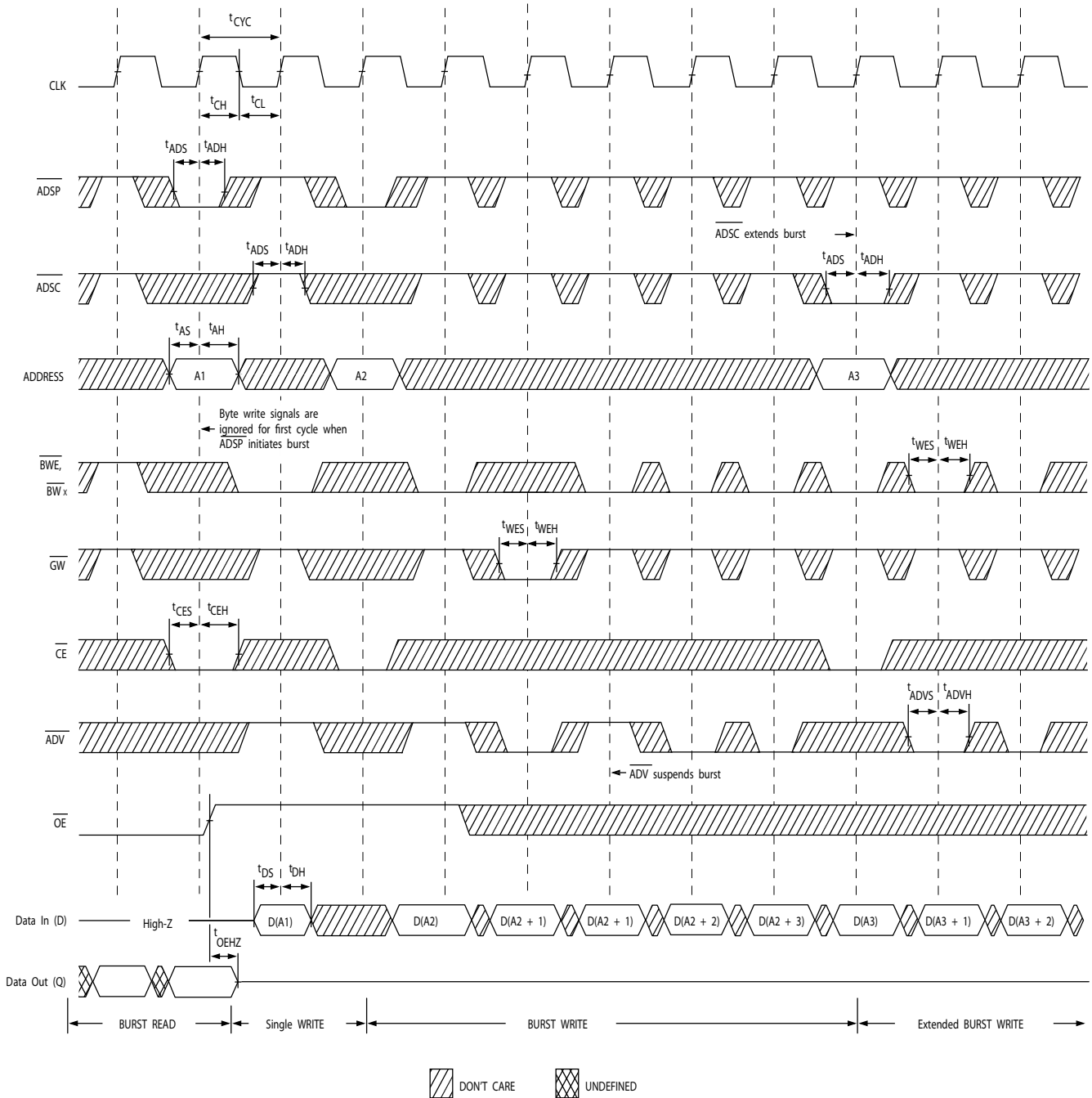
**Note**

27. On this diagram, when  $\overline{CE}$  is LOW:  $\overline{CE}_1$  is LOW,  $\overline{CE}_2$  is HIGH and  $\overline{CE}_3$  is LOW. When  $\overline{CE}$  is HIGH:  $\overline{CE}_1$  is HIGH or  $\overline{CE}_2$  is LOW or  $\overline{CE}_3$  is HIGH.



Switching Waveforms (continued)

Figure 7. Write Cycle Timing<sup>[28, 29]</sup>

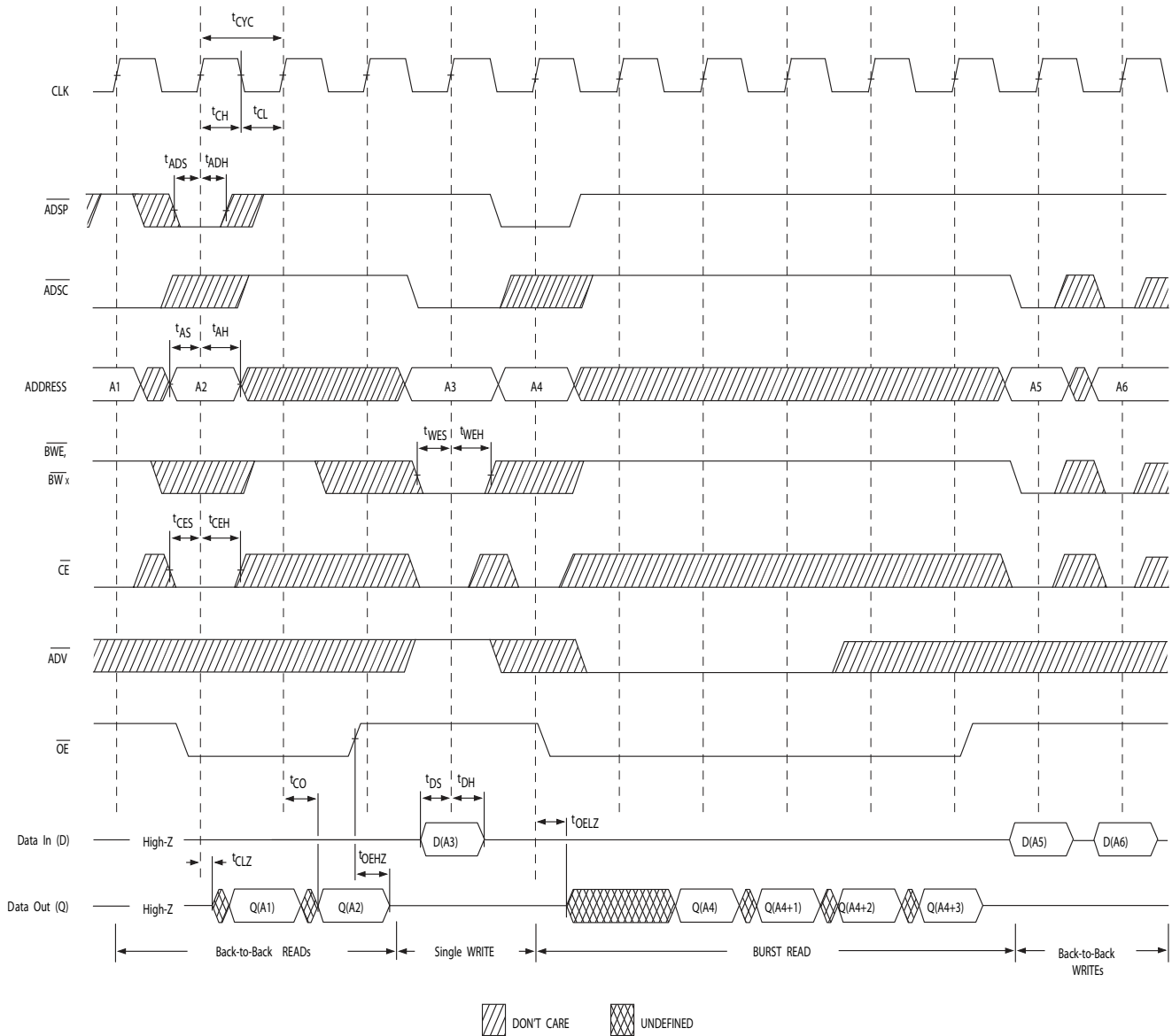


Notes

28. On this diagram, when  $\overline{CE}$  is LOW:  $\overline{CE}_1$  is LOW,  $CE_2$  is HIGH and  $\overline{CE}_3$  is LOW. When  $\overline{CE}$  is HIGH:  $\overline{CE}_1$  is HIGH or  $CE_2$  is LOW or  $\overline{CE}_3$  is HIGH.  
 29. Full width write can be initiated by either  $\overline{GW}$  LOW; or by  $\overline{GW}$  HIGH,  $\overline{BWE}$  LOW and  $\overline{BW}_X$  LOW.

Switching Waveforms (continued)

Figure 8. Read/Write Cycle Timing<sup>[30, 31, 32]</sup>

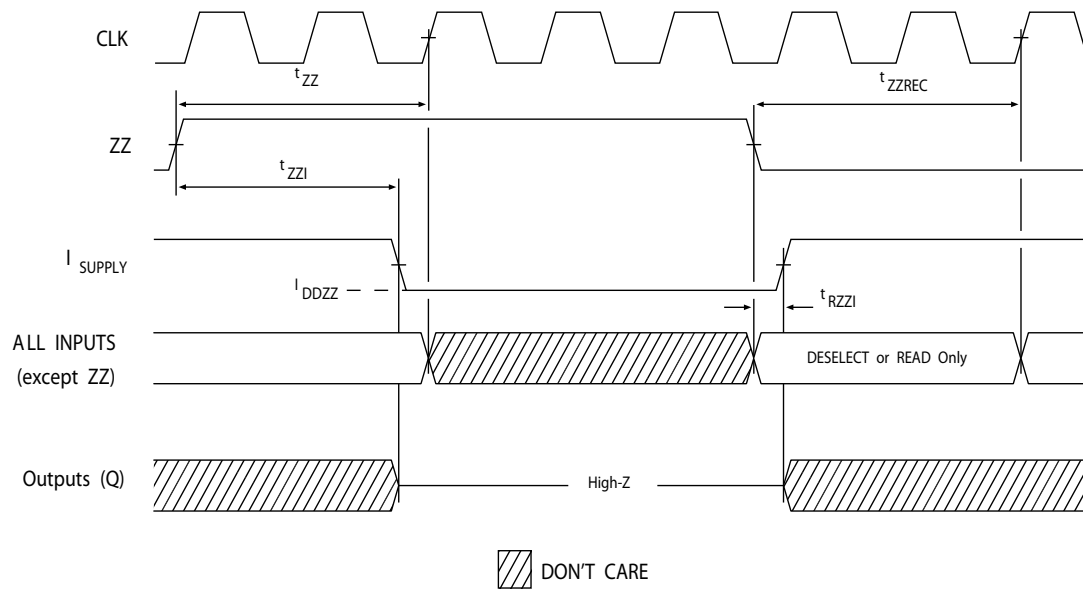


Notes

- 30. On this diagram, when  $\overline{CE}$  is LOW:  $\overline{CE}_1$  is LOW,  $CE_2$  is HIGH and  $\overline{CE}_3$  is LOW. When  $\overline{CE}$  is HIGH:  $\overline{CE}_1$  is HIGH or  $CE_2$  is LOW or  $\overline{CE}_3$  is HIGH.
- 31. The data bus (Q) remains in high Z following a write cycle, unless a new read access is initiated by ADSP or ADSC.
- 32.  $\overline{GW}$  is HIGH.

Switching Waveforms (continued)

Figure 9. ZZ Mode Timing<sup>[33, 34]</sup>



Notes

- 33. Device must be deselected when entering ZZ mode. See Cycle Descriptions table for all possible signal conditions to deselect the device.
- 34. DQs are in high Z when exiting ZZ sleep mode.

## Ordering Information

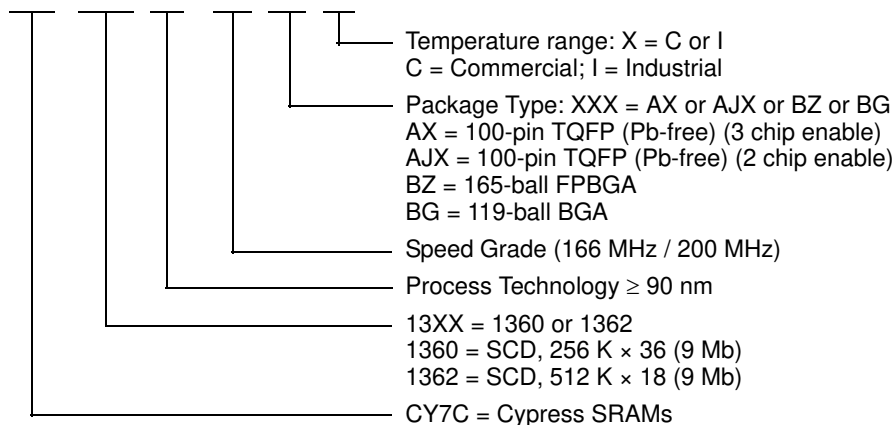
The table below contains only the parts that are currently available. If you don't see what you are looking for, please contact your local sales representative. For more information, visit the Cypress website at [www.cypress.com](http://www.cypress.com) and refer to the product summary page at <http://www.cypress.com/products>

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Speed (MHz)	Ordering Code	Package Diagram	Part and Package Type	Operating Range
166	CY7C1360C-166AXC	51-85050	100-pin Thin Quad Flat Pack (14 × 20 × 1.4 mm) Pb-free (3 chip enable)	Commercial
	CY7C1360C-166AJXC	51-85050	100-pin Thin Quad Flat Pack (14 × 20 × 1.4 mm) Pb-free (2 chip enable)	
	CY7C1362C-166AJXC			
	CY7C1360C-166BZC	51-85180	165-ball Fine-Pitch Ball Grid Array (13 × 15 × 1.4 mm)	
	CY7C1360C-166AXI	51-85050	100-pin Thin Quad Flat Pack (14 × 20 × 1.4 mm) Pb-free (3 chip enable)	Industrial
200	CY7C1360C-200AXC	51-85050	100-pin Thin Quad Flat Pack (14 × 20 × 1.4 mm) Pb-free (3 chip enable)	Commercial
	CY7C1360C-200AJXC	51-85050	100-pin Thin Quad Flat Pack (14 × 20 × 1.4 mm) Pb-free (2 chip enable)	
	CY7C1360C-200BGC	51-85115	119-ball Ball Grid Array (14 × 22 × 2.4 mm)	

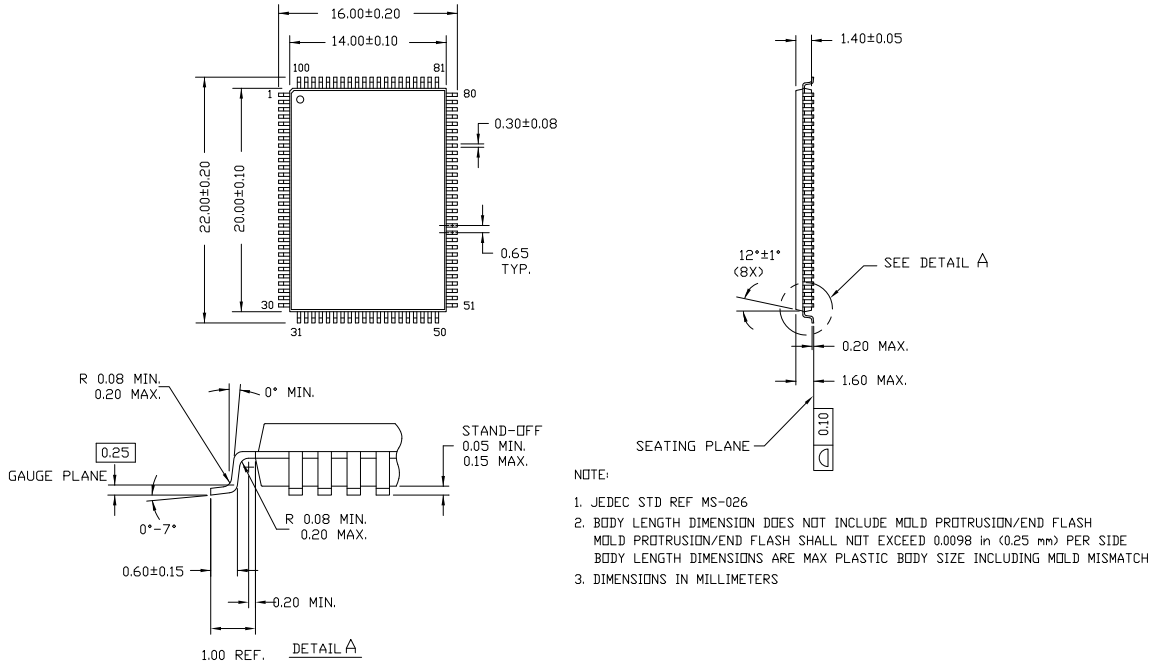
## Ordering Code Definitions

CY7C 13XX C - XXX XXX X



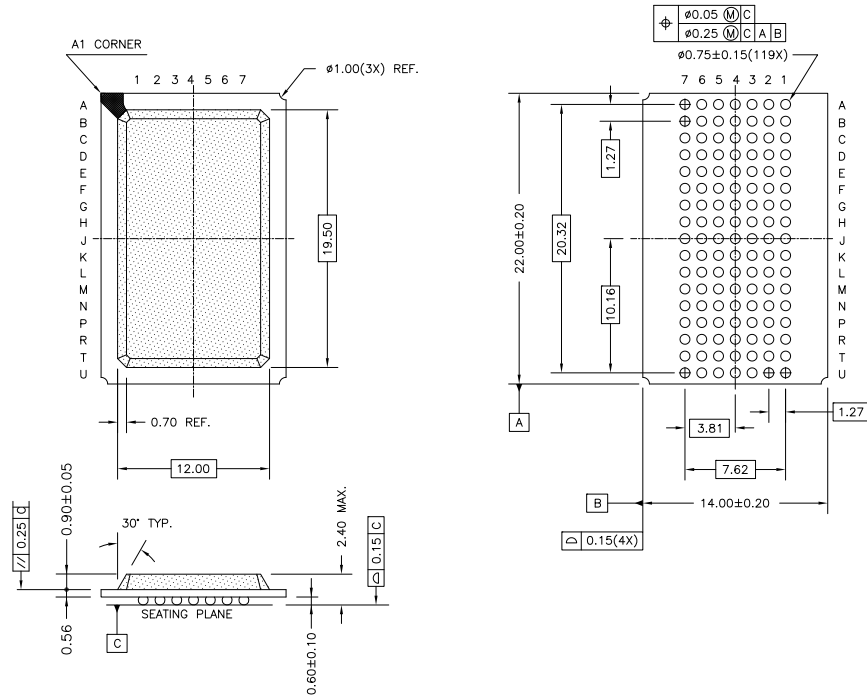
Package Diagrams

Figure 10. 100-pin Thin Plastic Quad Flatpack (14 × 20 × 1.4 mm)



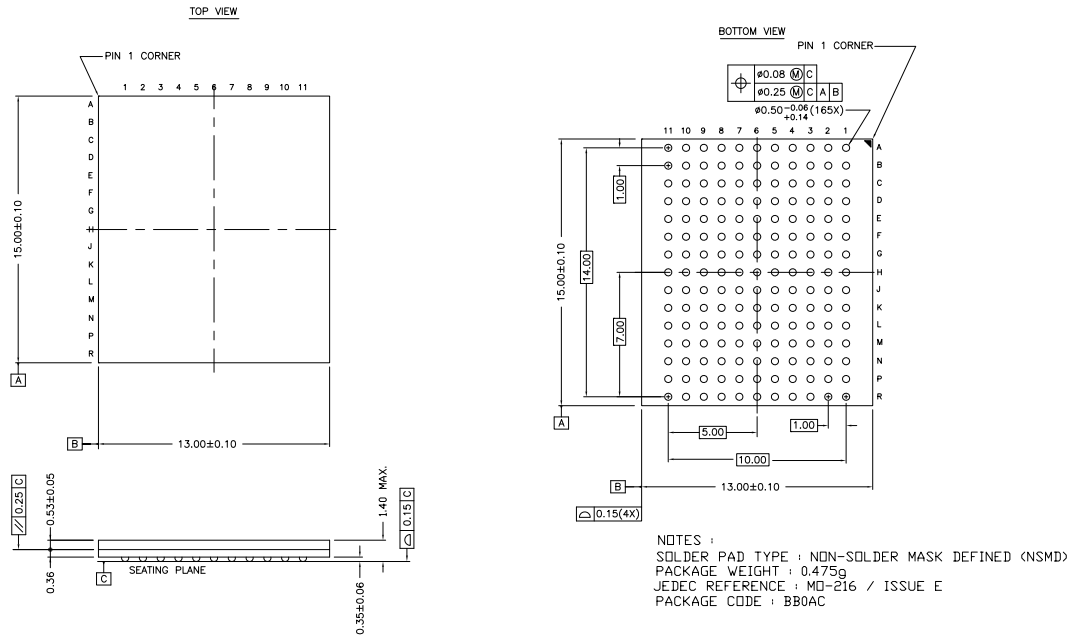
51-85050 \*C

**Figure 11. 119-ball PBGA (14 × 22 × 2.4 mm)**



51-85115 °C

**Figure 12. 165-ball FBGA (13 x 15 x 1.4 mm)**



51-85180 \*C

**Acronyms**

Acronym	Description
BGA	ball grid array
CE	chip enable
CEN	clock enable
FPBGA	fine-pitch ball grid array
I/O	input/output
JTAG	Joint Test Action Group
OE	output enable
SRAM	static random access memory
TCK	test clock
TMS	test mode select
TDI	test data-in
TDO	test data-out
TQFP	thin quad flat pack
WE	write enable

**Document Conventions**

**Units of Measure**

Symbol	Unit of Measure
ns	nano seconds
V	Volts
μA	micro Amperes
mA	milli Amperes
ms	milli seconds
MHz	Mega Hertz
pF	pico Farad
W	Watts
°C	degree Celcius



**Document History Page**

Document Title: CY7C1360C/CY7C1362C 9-Mbit (256 K × 36/512 K × 18) Pipelined SRAM Document Number: 38-05540				
REV.	ECN NO.	Submission Date	Orig. of Change	Description of Change
**	241690	See ECN	RKF	New data sheet
*A	278130	See ECN	RKF	Changed Boundary Scan order to match the B rev of these devices Changed TQFP pkg to Lead-free TQFP in Ordering Information section Added comment of Lead-free BG and BZ packages availability
*B	248929	See ECN	VBL	Changed ISB1 and ISB3 from DC Characteristics table as follows: ISB1: 225 MHz -> 130 mA, 200 MHz -> 120 mA, 167 MHz -> 110 mA ISB3: 225 MHz -> 120 mA, 200 MHz -> 110 mA, 167 MHz -> 100 mA Changed IDDZZ to 50 mA Added BG and BZ pkg lead-free part numbers to ordering info section
*C	323636	See ECN	PCI	Changed frequency of 225 MHz into 250 MHz Added $t_{CYC}$ of 4.0 ns for 250 MHz Changed $\theta_{JA}$ and $\theta_{JC}$ for TQFP Package from 25 and 9 °C/W to 29.41 and 6.13 °C/W respectively Changed $\theta_{JA}$ and $\theta_{JC}$ for BGA Package from 25 and 6 °C/W to 34.1 and 14.0 °C/W respectively Changed $\theta_{JA}$ and $\theta_{JC}$ for FBGA Package from 27 and 6 °C/W to 16.8 and 3.0 °C/W respectively Modified address expansion as per JEDEC Standard Removed comment of Lead-free BG and BZ packages availability
*D	332879	See ECN	PCI	Unshaded 200 and 166 MHz speed bins in the AC/DC Table and Selection Guide Added Address Expansion pins in the Pin Definition Table Changed Device Width (23:18) for 119-BGA from 000000 to 101000 Added separate row for 165 -FBGA Device Width (23:18) Modified $V_{OL}$ , $V_{OH}$ test conditions Updated Ordering Information Table
*E	357258	See ECN	PCI	Changed from Preliminary to Final Removed Shading on 250MHz Speed Bin in Selection Guide and AC/DC Table Changed $I_{SB2}$ from 30 to 40 mA Updated Ordering Information Table
*F	377095	See ECN	PCI	Modified test condition in note# 16 from $V_{DDQ} < V_{DD}$ to $V_{DDQ} \leq V_{DD}$
*G	408298	See ECN	RXU	Changed address of Cypress Semiconductor Corporation on Page# 1 from "3901 North First Street" to "198 Champion Court" Changed three-state to tri-state on page# 9 & page# 10 Modified "Input Load" to "Input Leakage Current except ZZ and MODE" in the Electrical Characteristics Table Replaced Package Name column with Package Diagram in the Ordering Information table Updated Ordering Information Table
*H	501793	See ECN	VKN	Added the Maximum Rating for Supply Voltage on $V_{DDQ}$ Relative to GND Changed $t_{TH}$ , $t_{TL}$ from 25 ns to 20 ns and $t_{TDOV}$ from 5 ns to 10 ns in TAP AC Switching Characteristics table. Updated the Ordering Information table.

**Document History Page** *(continued)*

<b>Document Title: CY7C1360C/CY7C1362C 9-Mbit (256 K x 36/512 K x 18)</b> <b>Pipelined SRAM</b> <b>Document Number: 38-05540</b>				
REV.	ECN NO.	Submission Date	Orig. of Change	Description of Change
*I	2756340	08/26/2009	VKN/AESA	Updated template Included Soft Error Immunity Data Modified Ordering Information table by including parts that are available and modified the disclaimer for the Ordering information.
*J	3046851	10/04/2010	NJY	Added <a href="#">Ordering Code Definitions</a> . Updated <a href="#">Package Diagrams</a> . Added <a href="#">Acronyms</a> and <a href="#">Units of Measure</a> . Minor edits and updated in new template.
*K	3052882	10/11/2010	NJY	Removed obsolete part.

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